

FIG. 1A

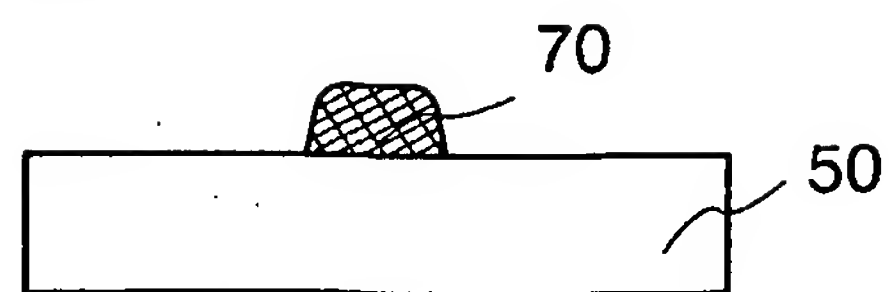


FIG. 1B

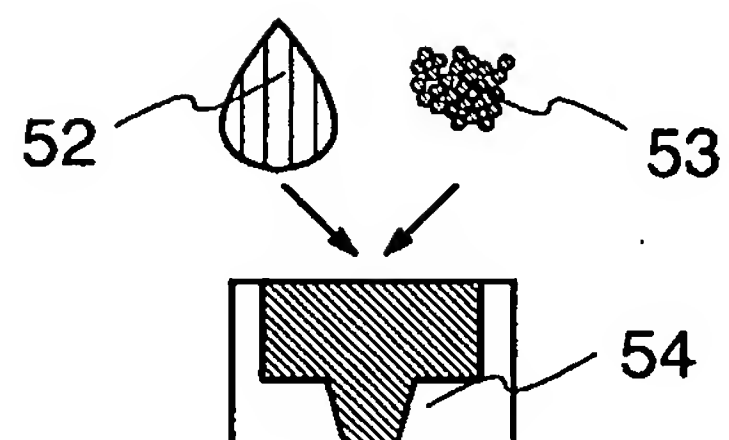


FIG. 1D

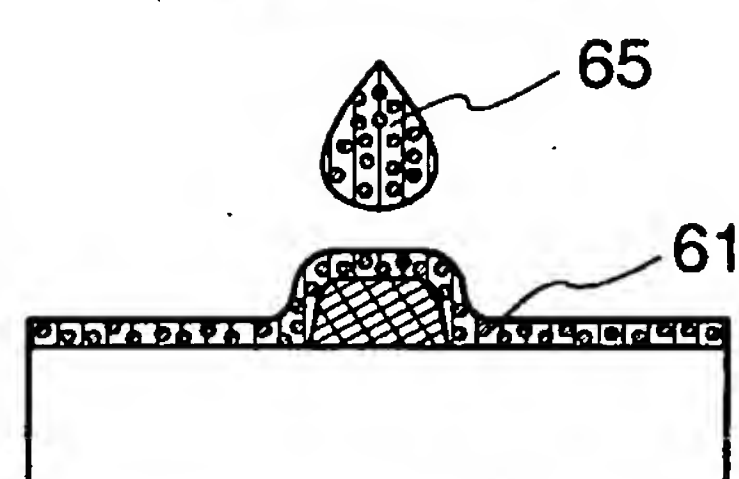
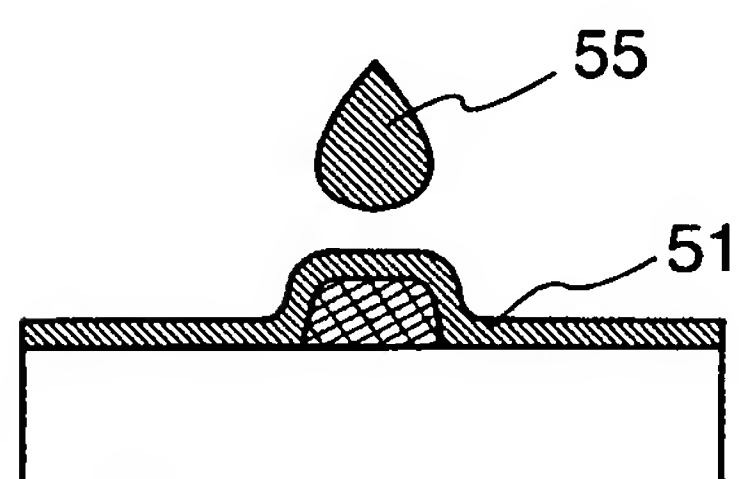
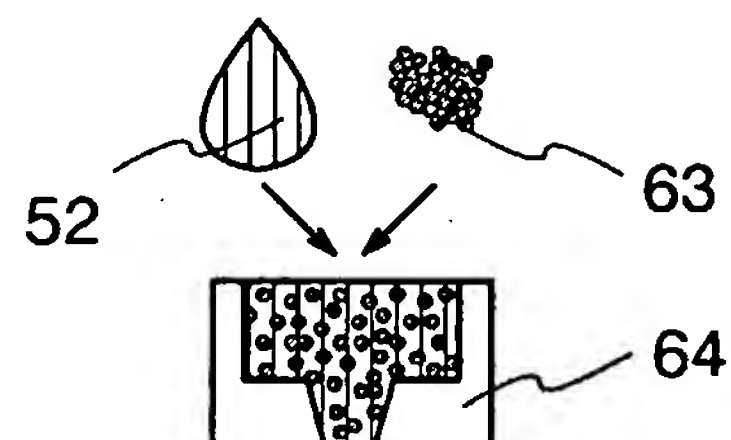


FIG. 1C

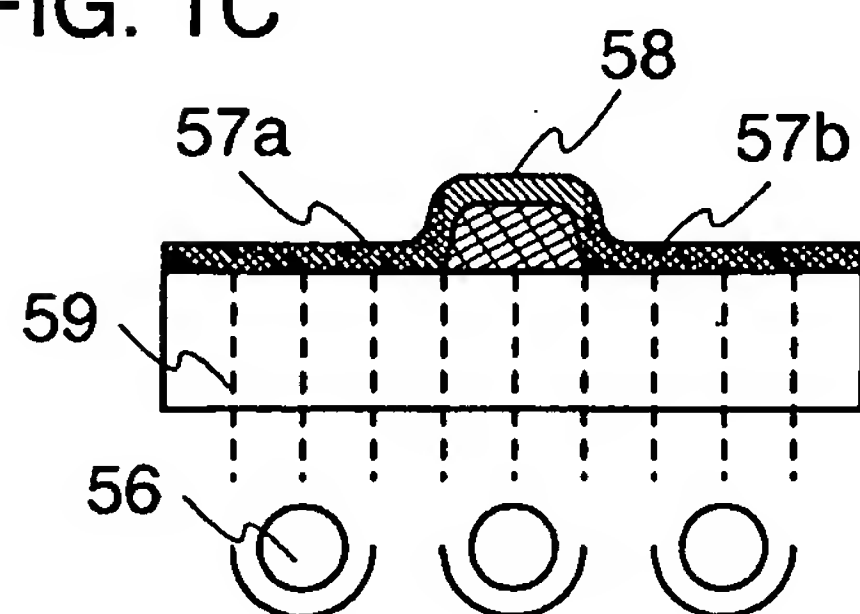


FIG. 1E

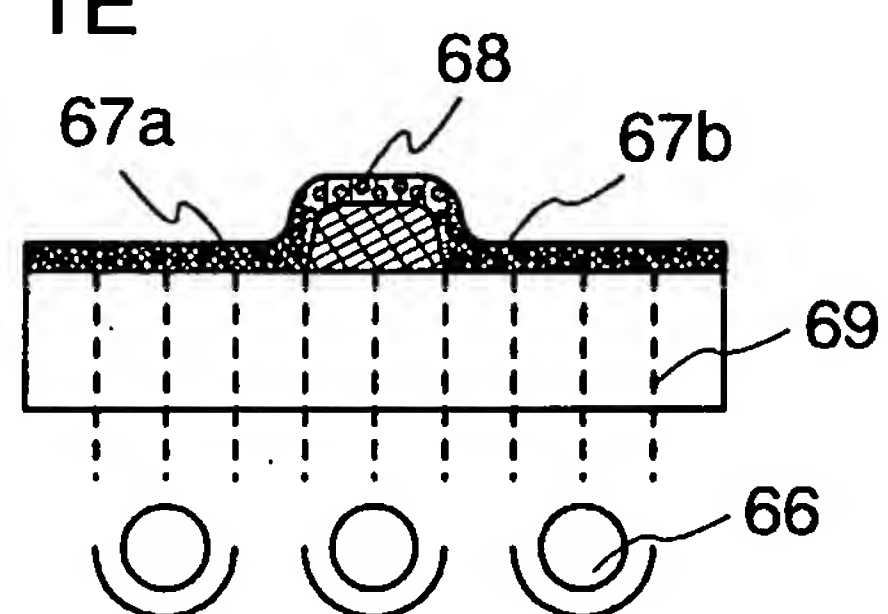


FIG. 1F

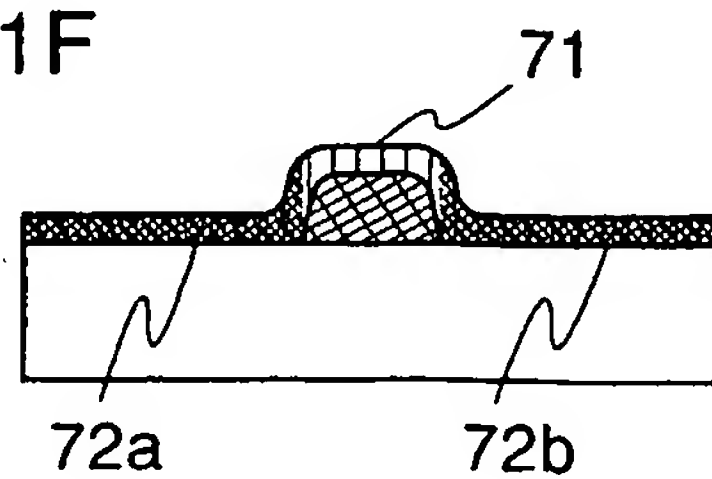


FIG. 2A

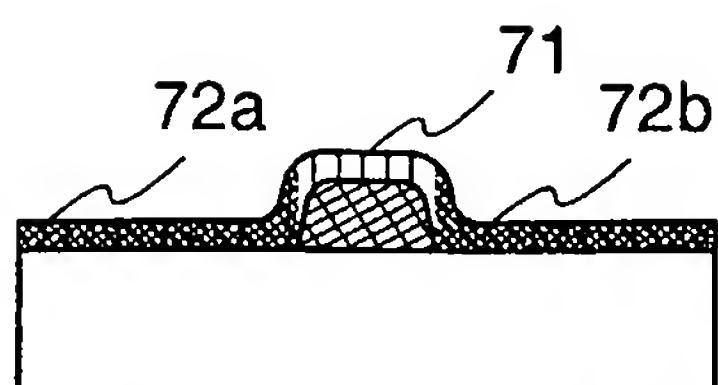


FIG. 2B

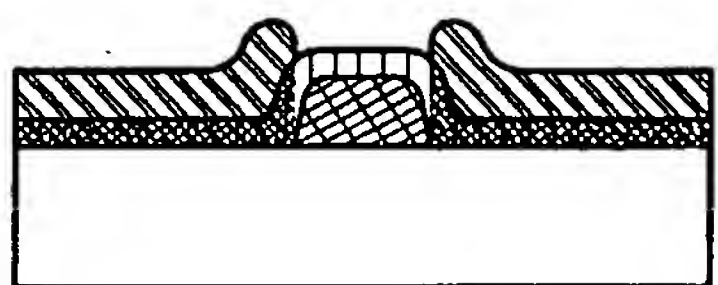
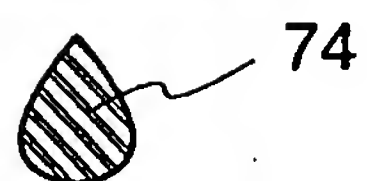


FIG. 2C

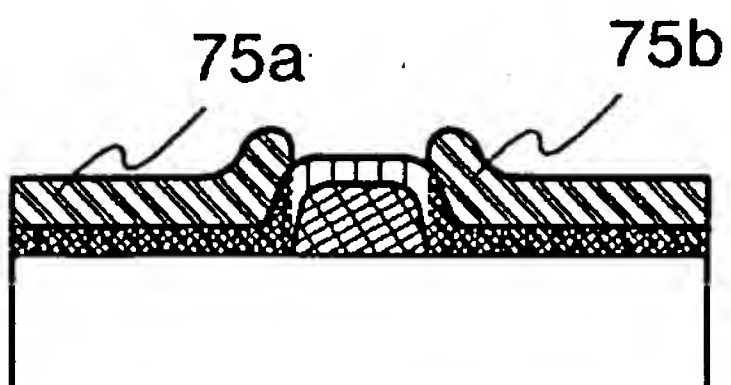


FIG. 3A

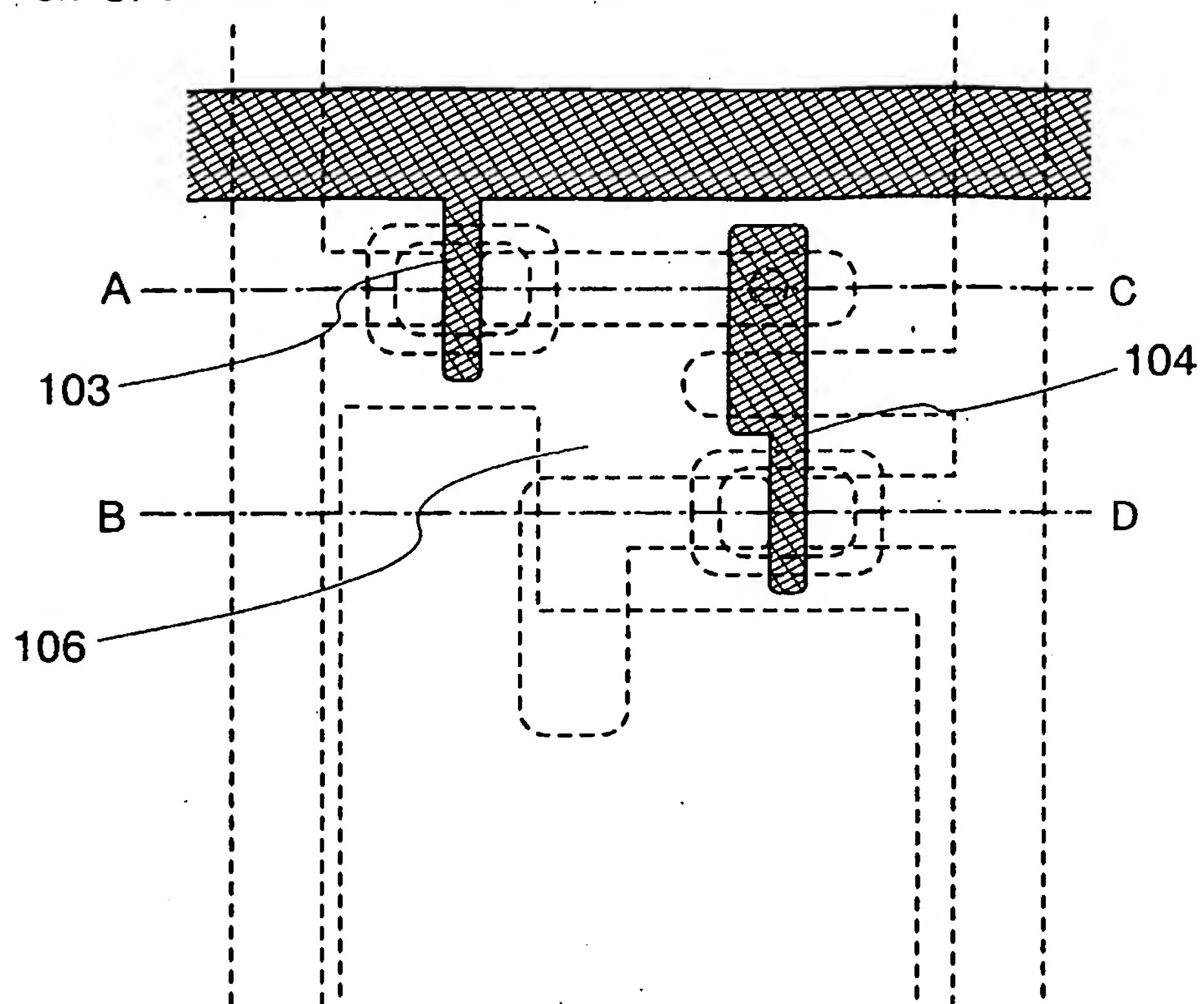


FIG. 3B

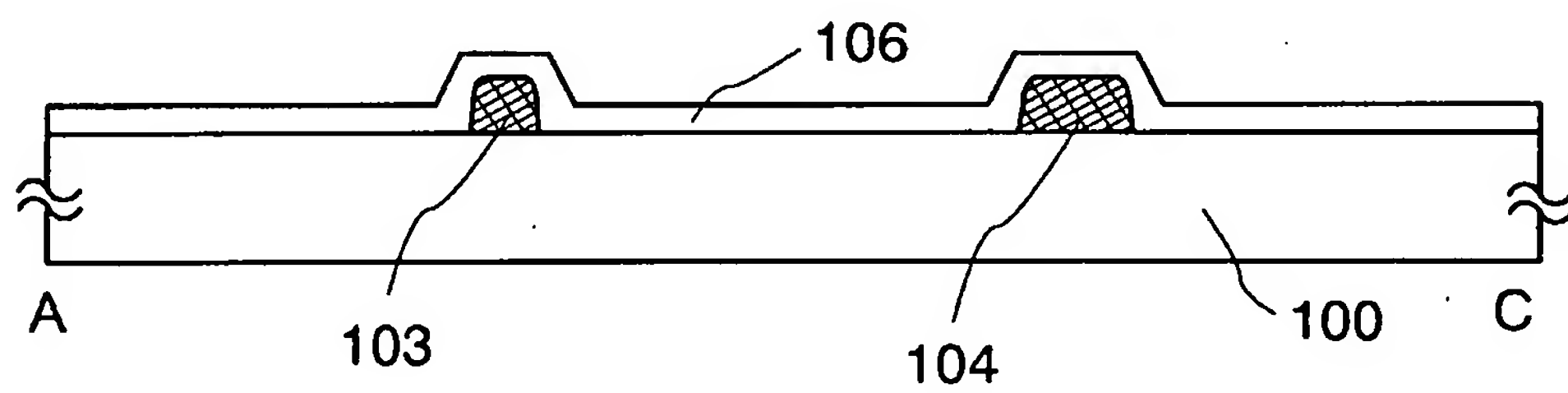


FIG. 3C

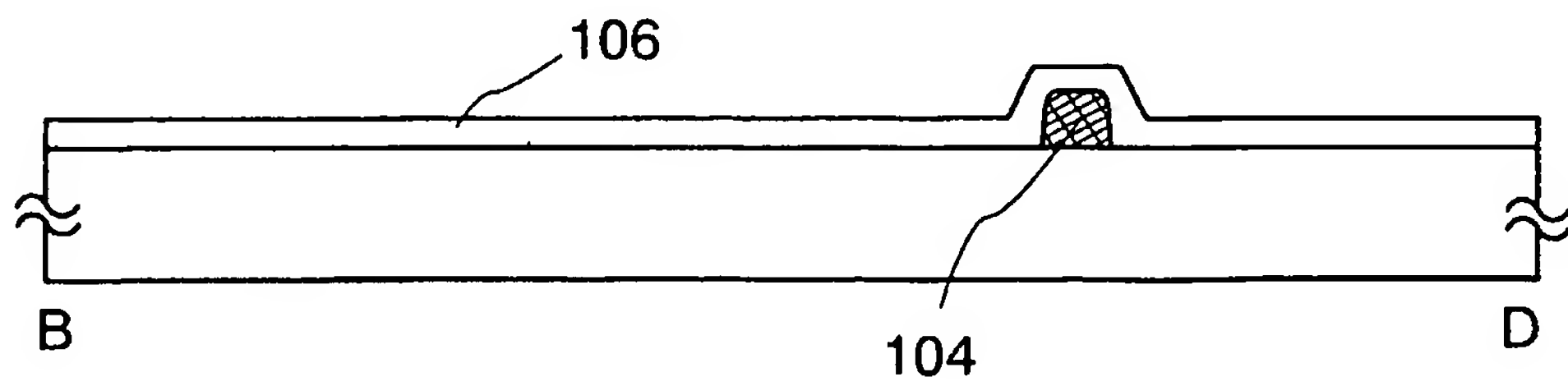


FIG. 4A

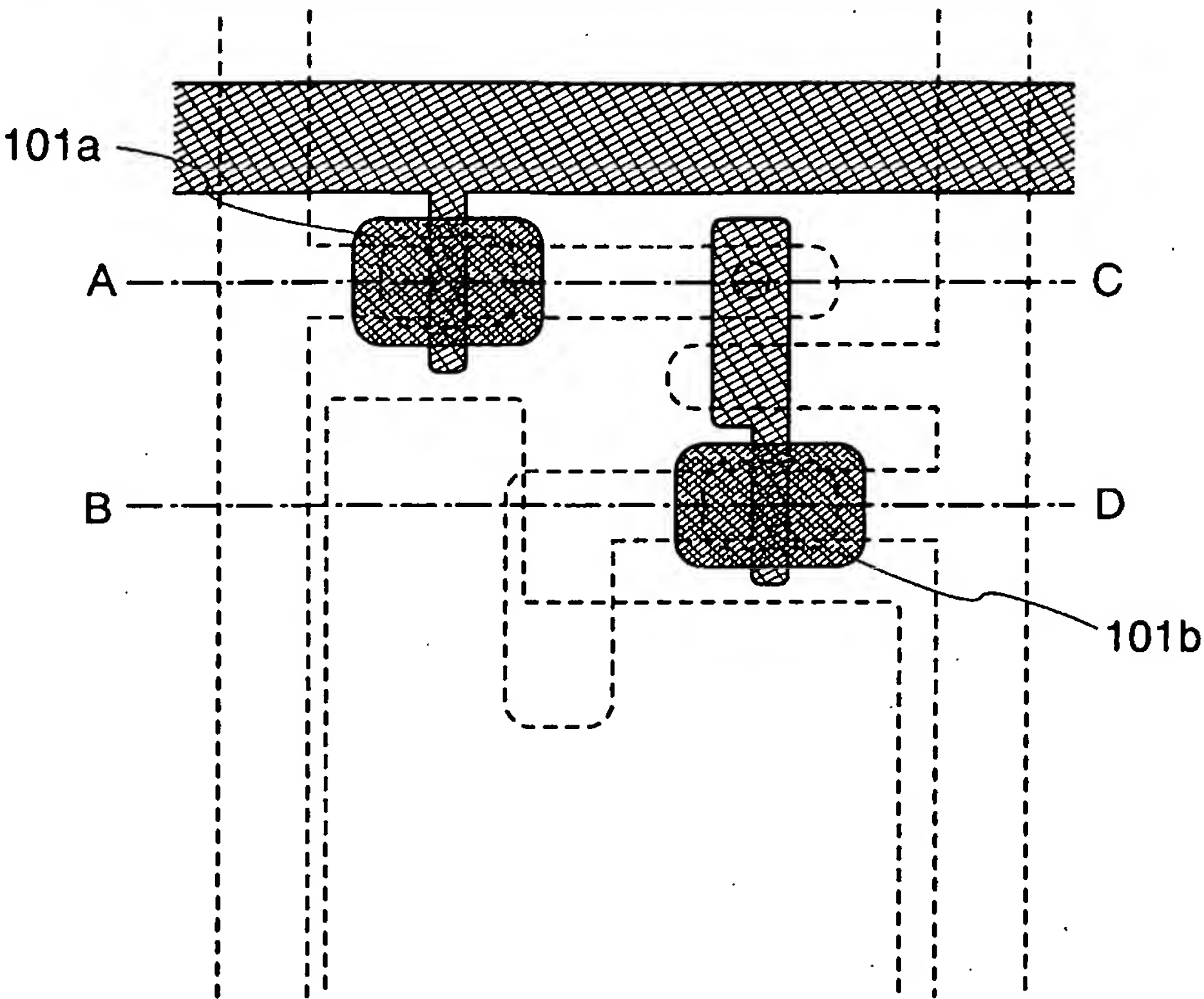


FIG. 4B

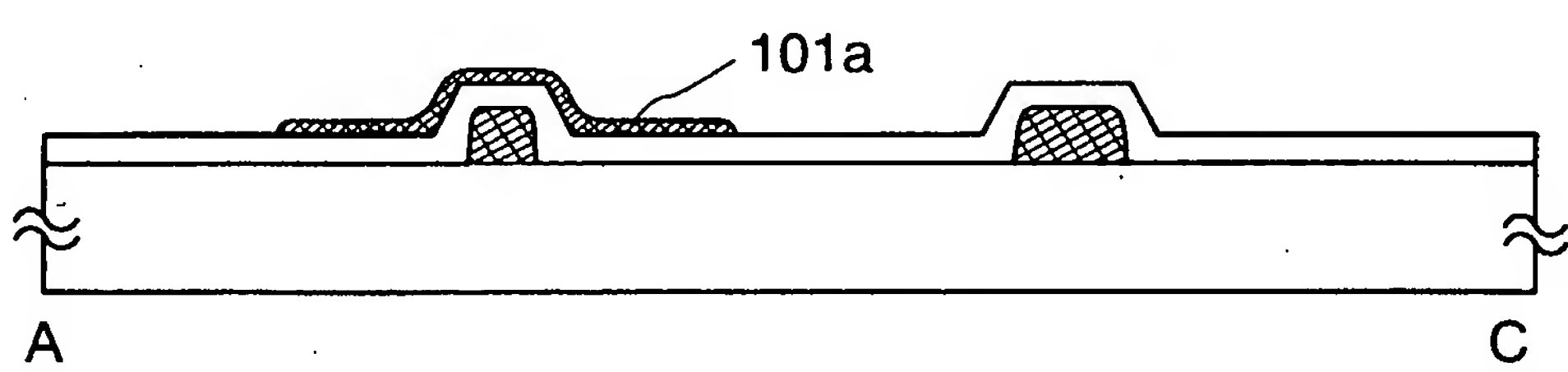


FIG. 4C

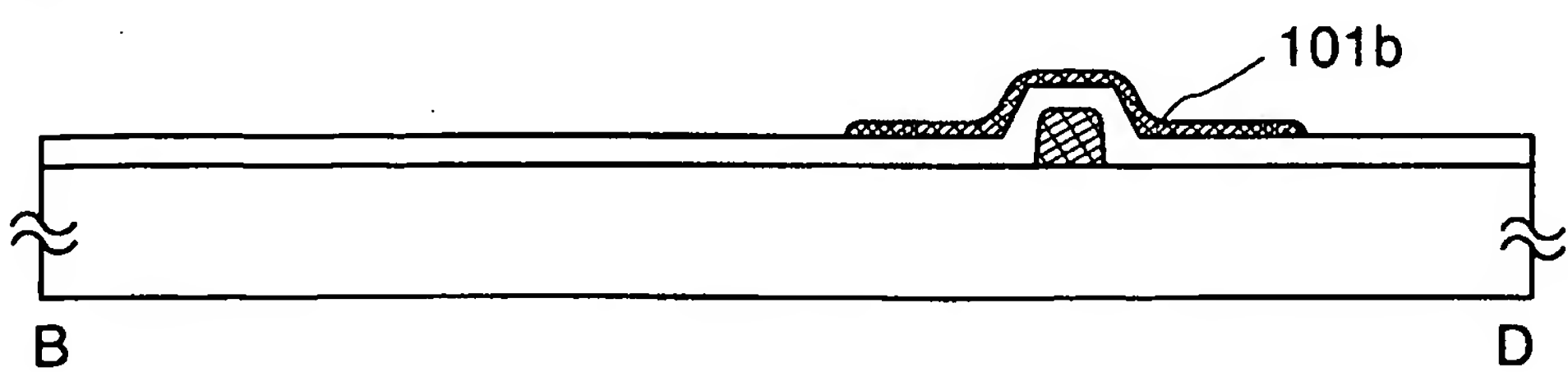


FIG. 5A

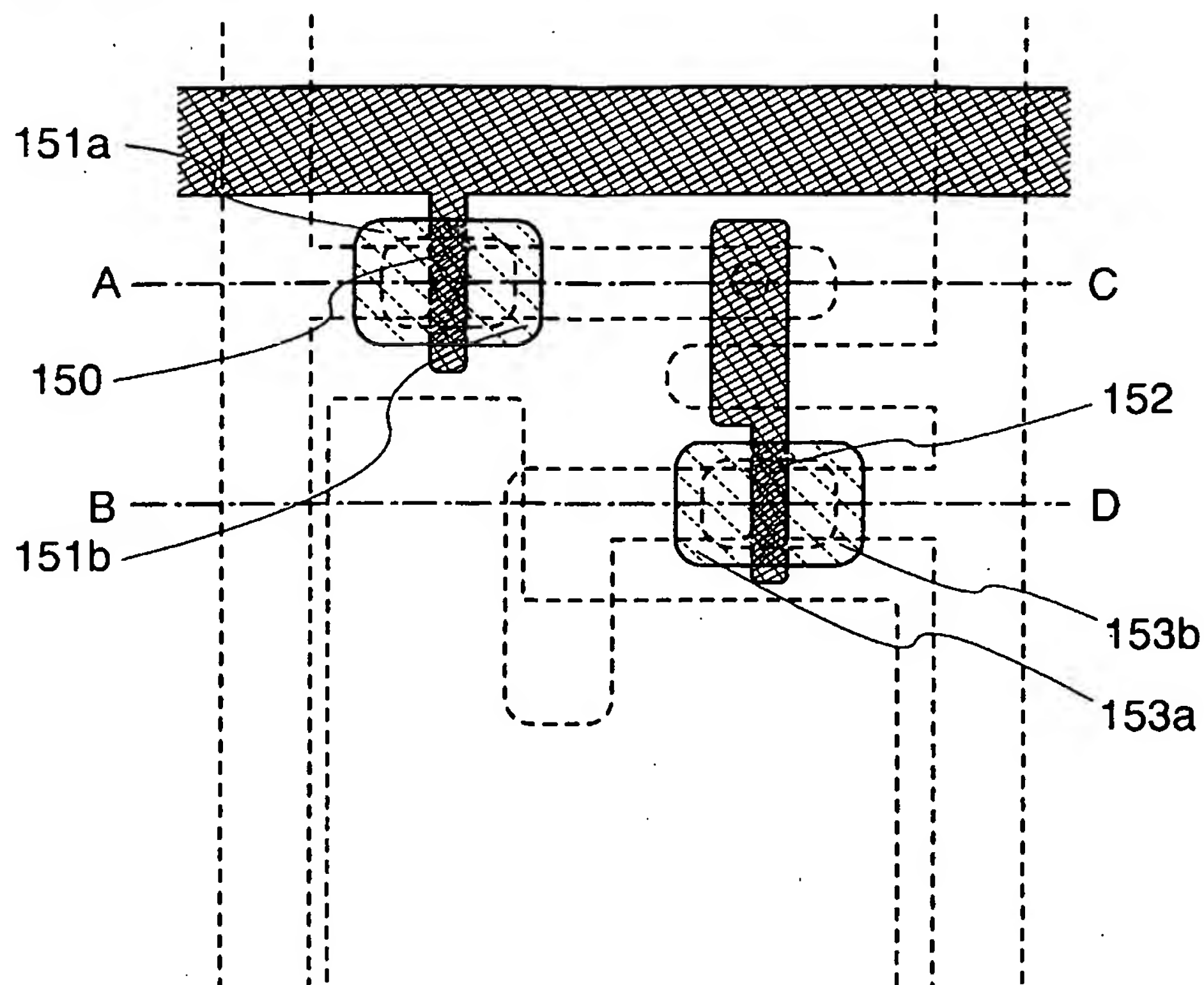


FIG. 5B

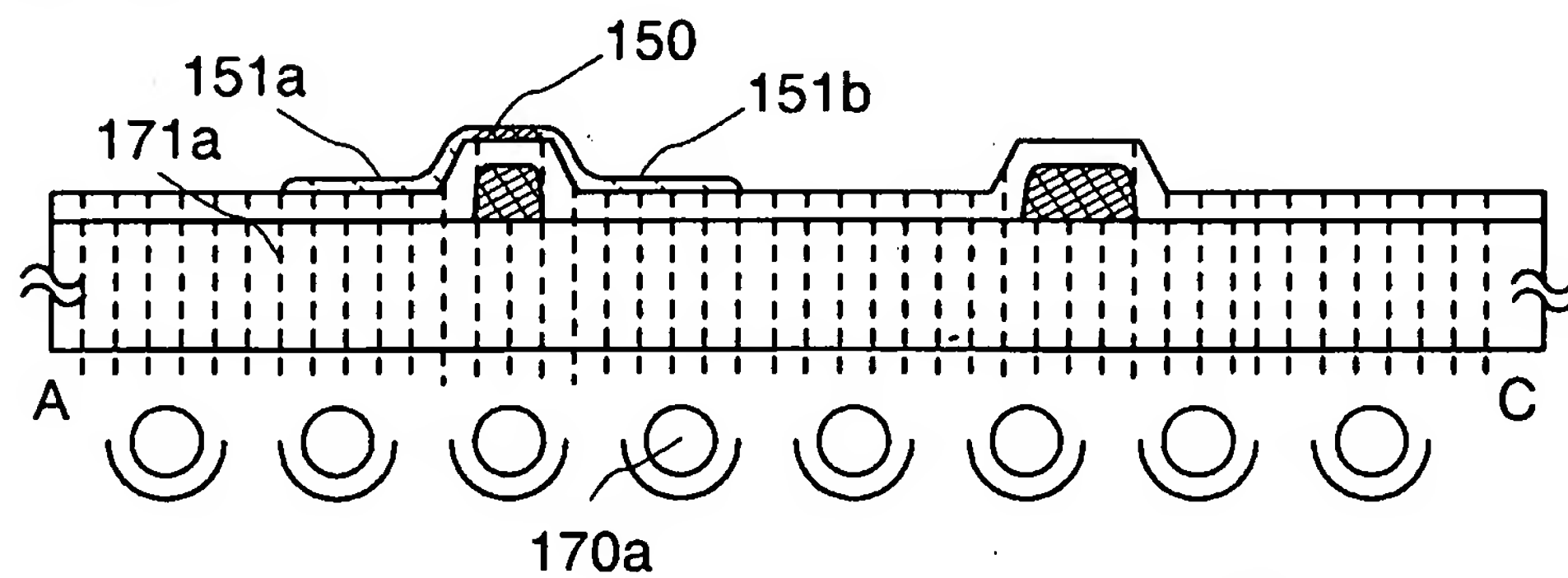


FIG. 5C

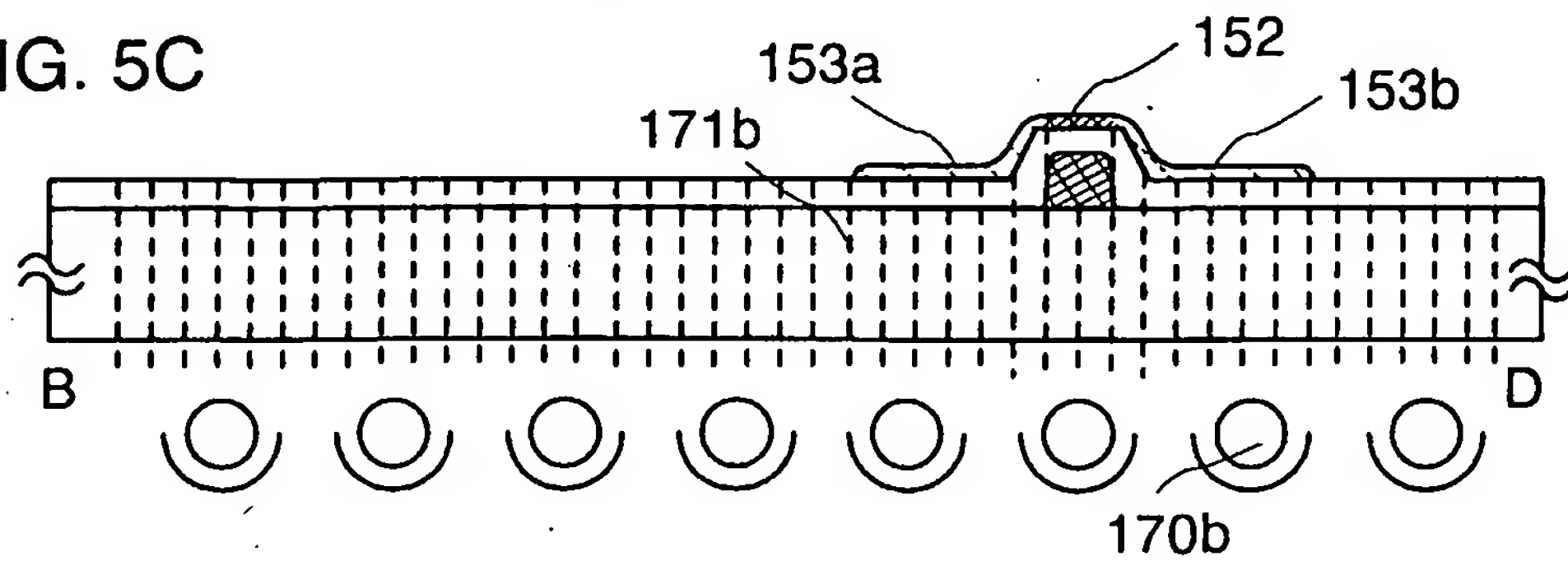


FIG. 6A

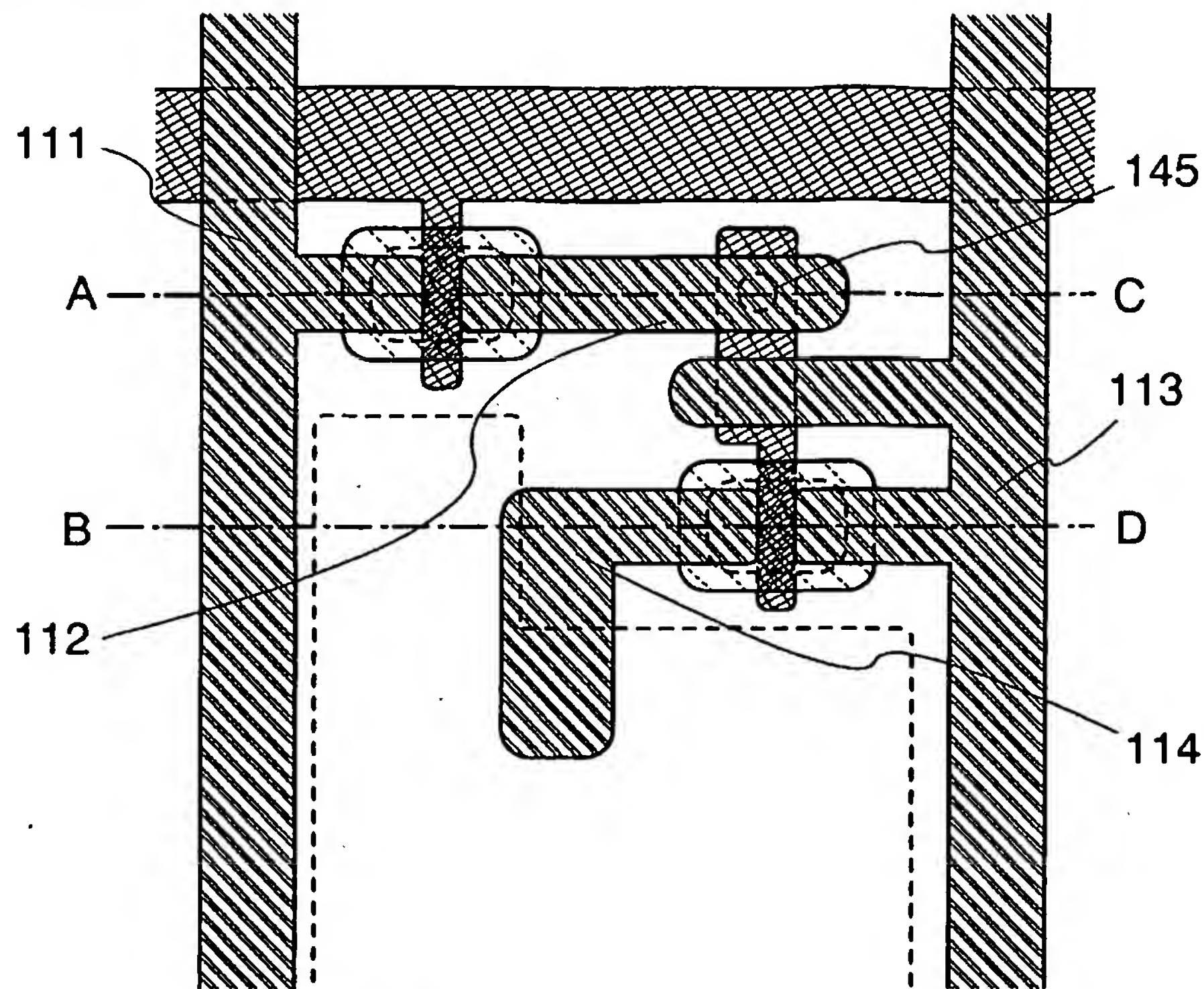


FIG. 6B

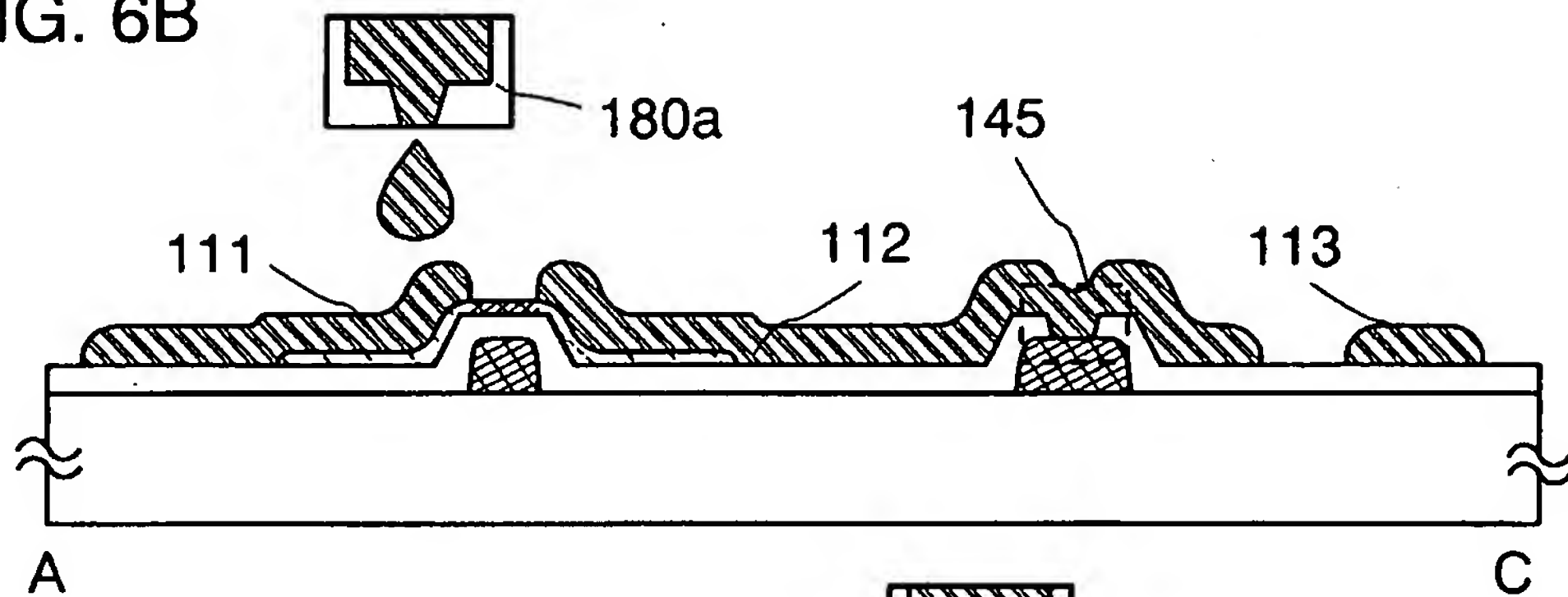


FIG. 6C

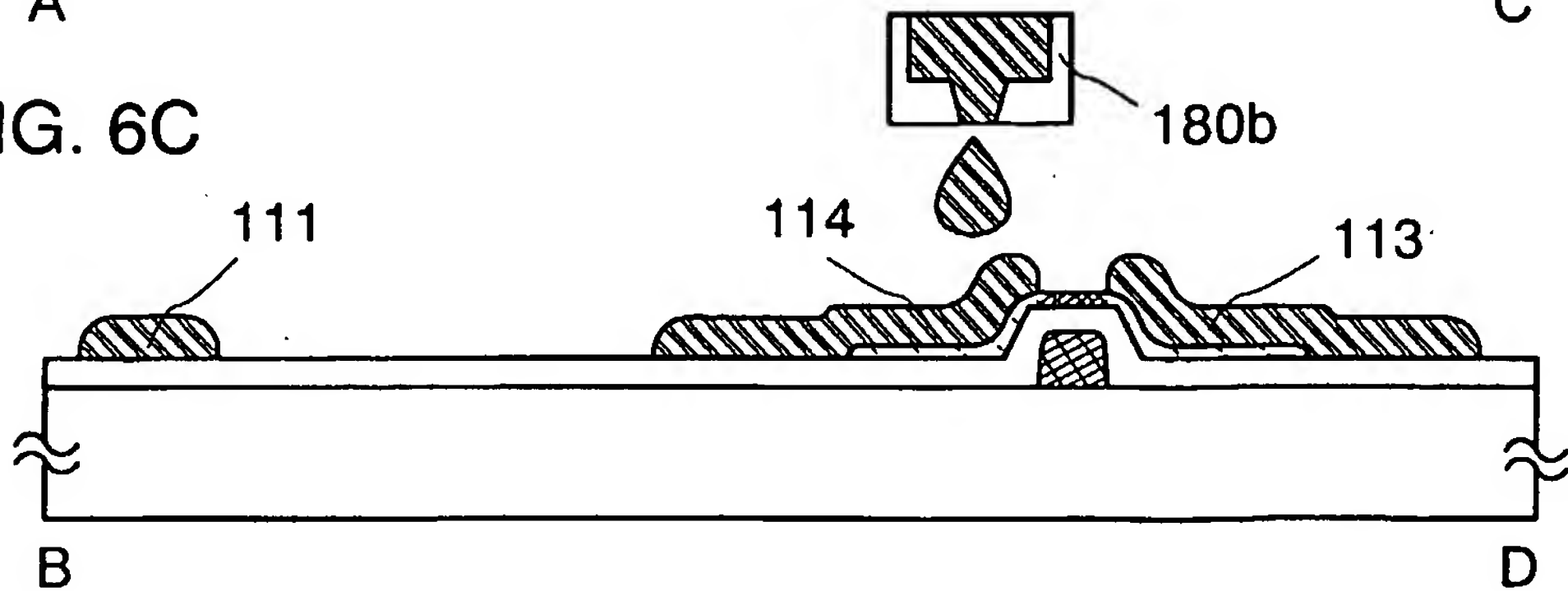


FIG. 7A

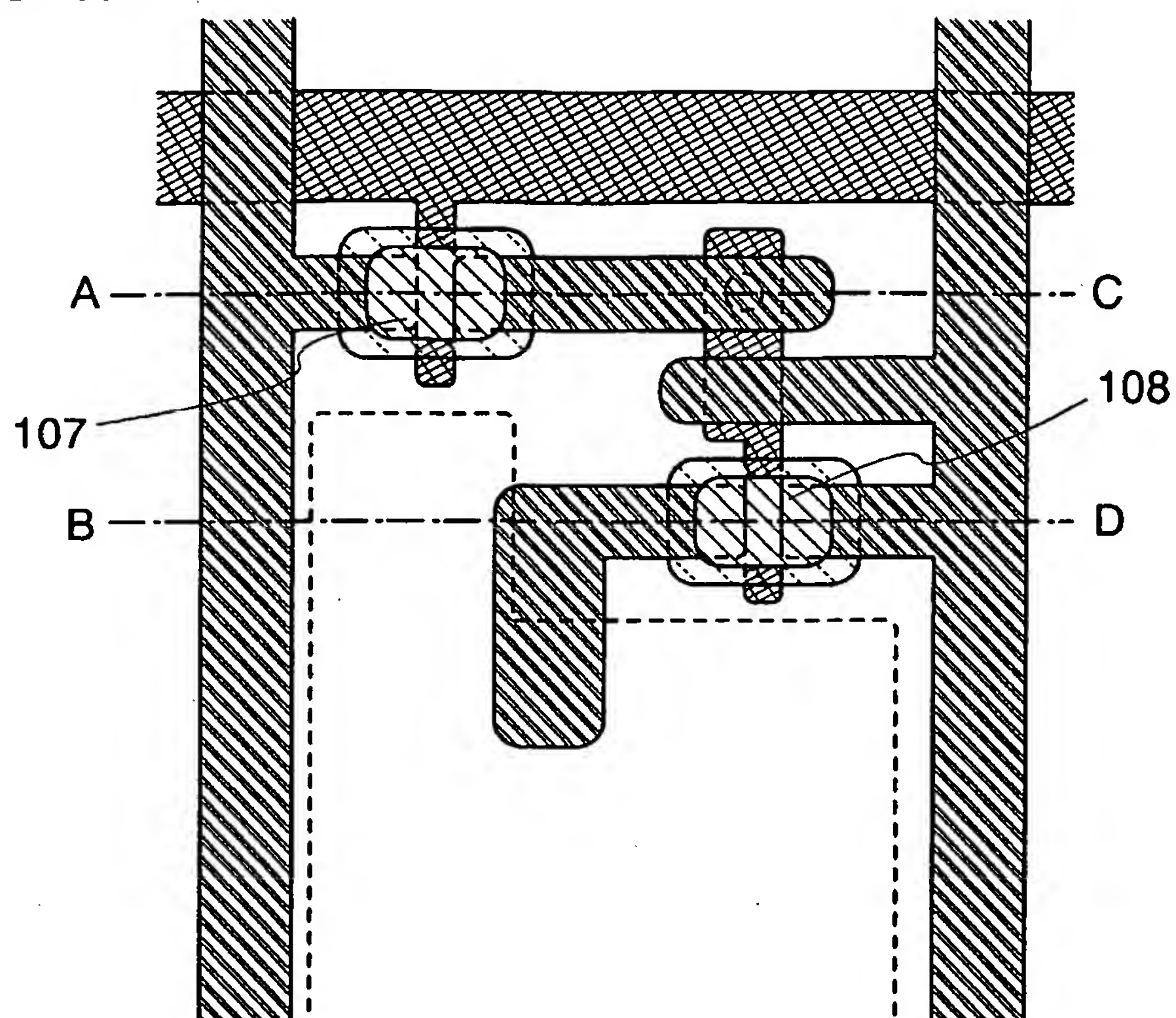


FIG. 7B

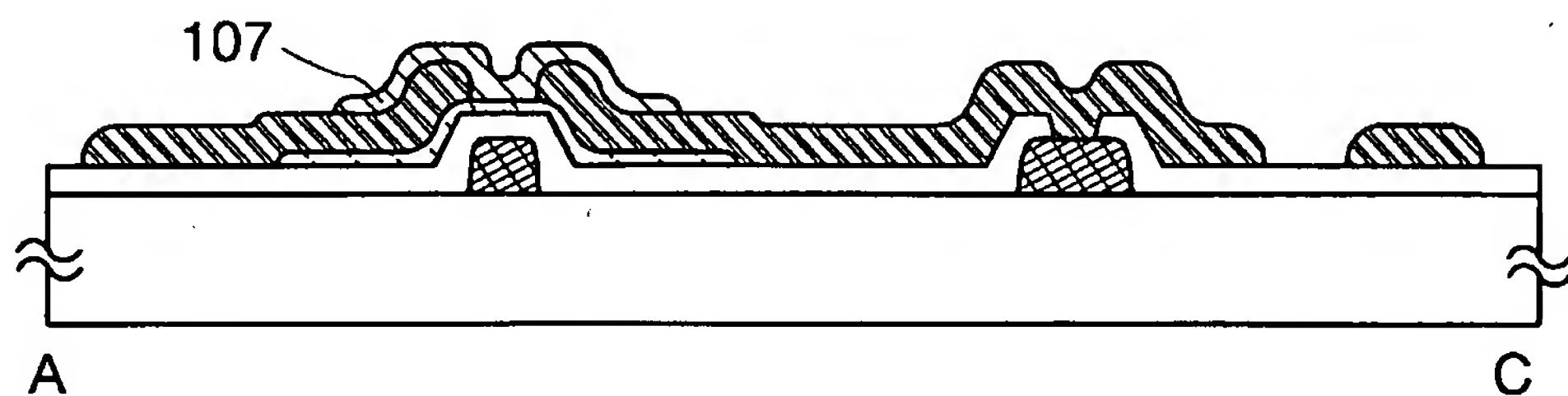


FIG. 7C

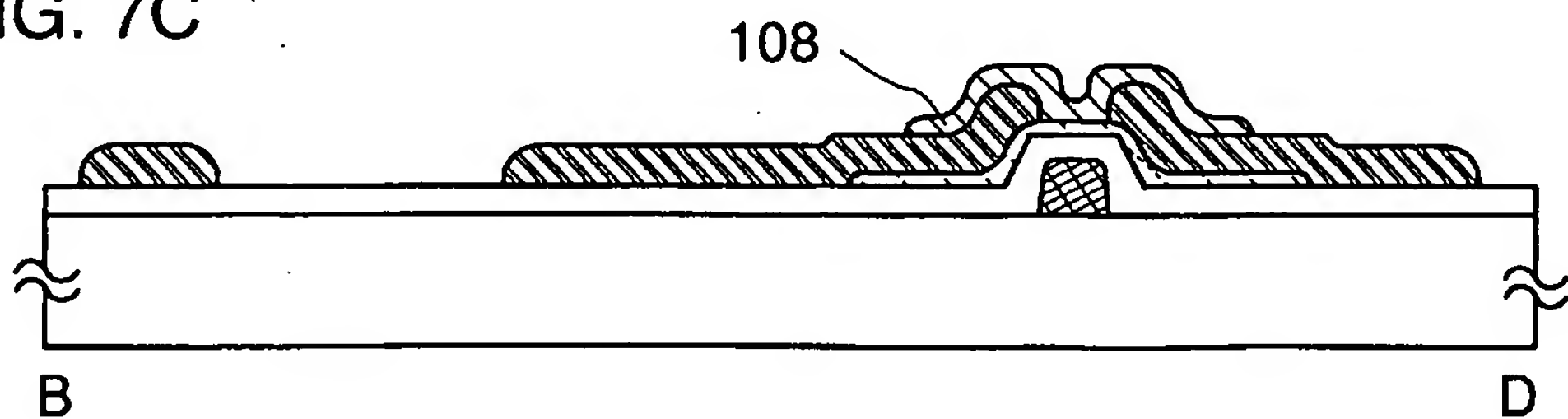


FIG. 8A

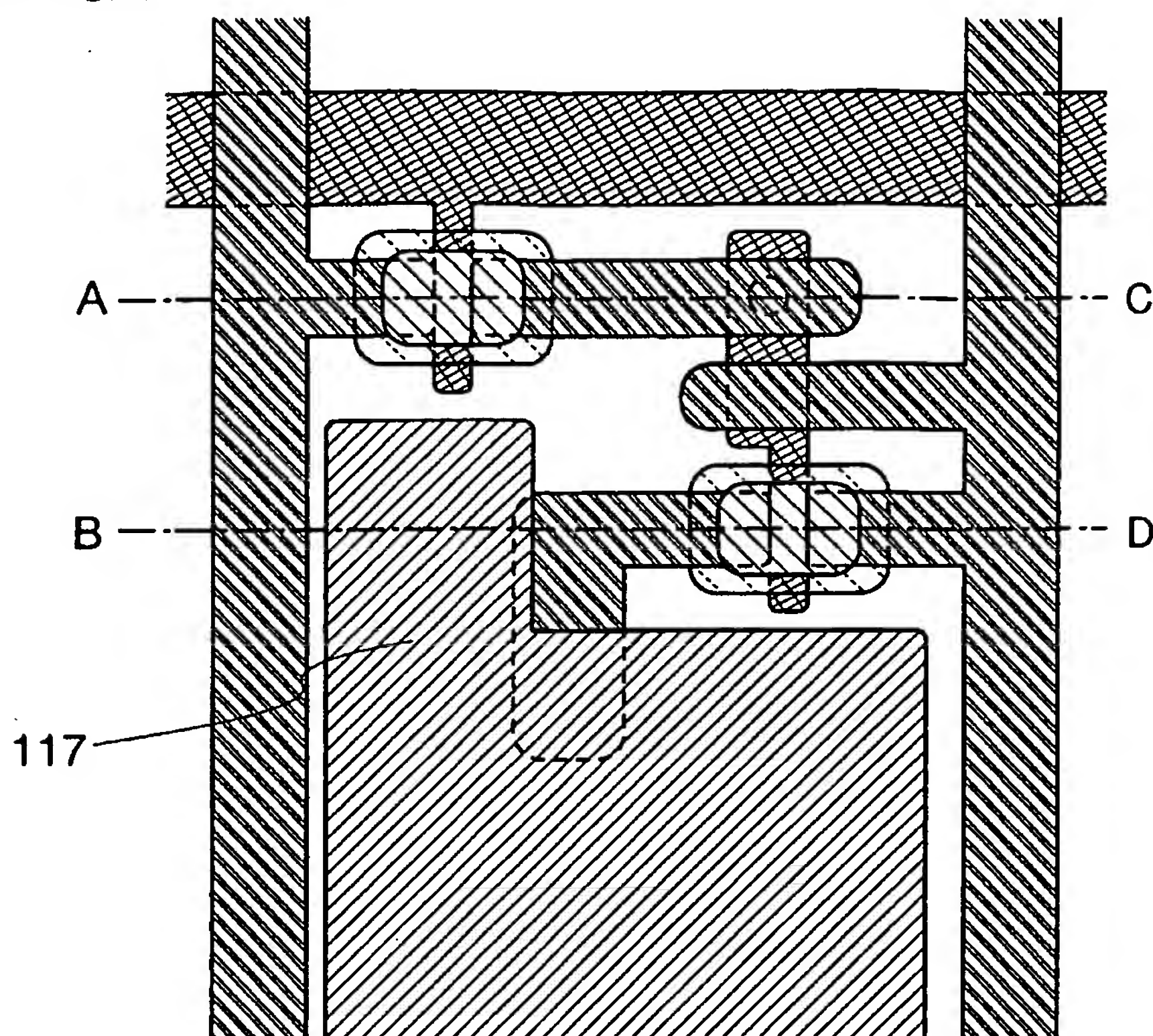


FIG. 8B

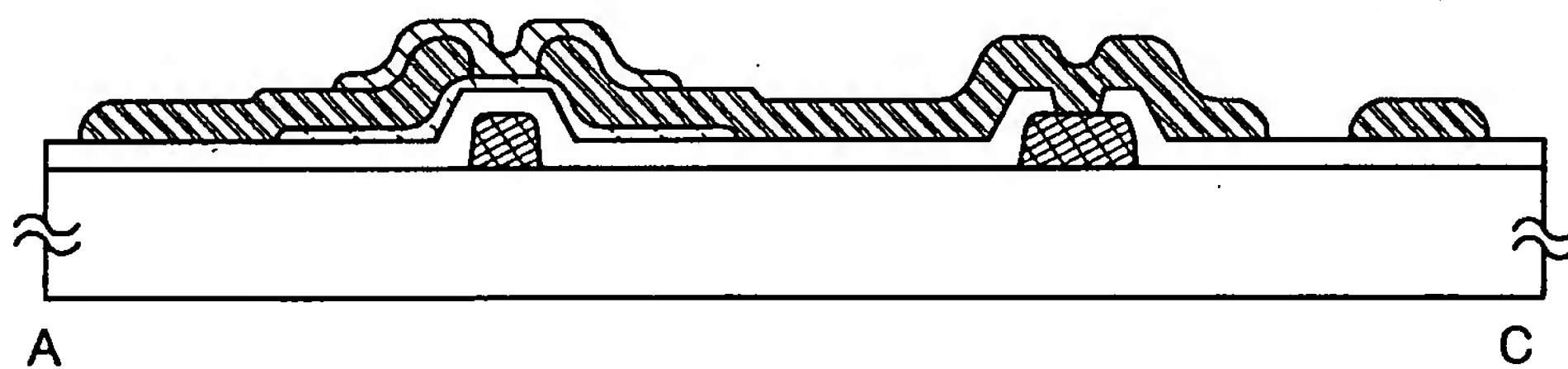


FIG. 8C

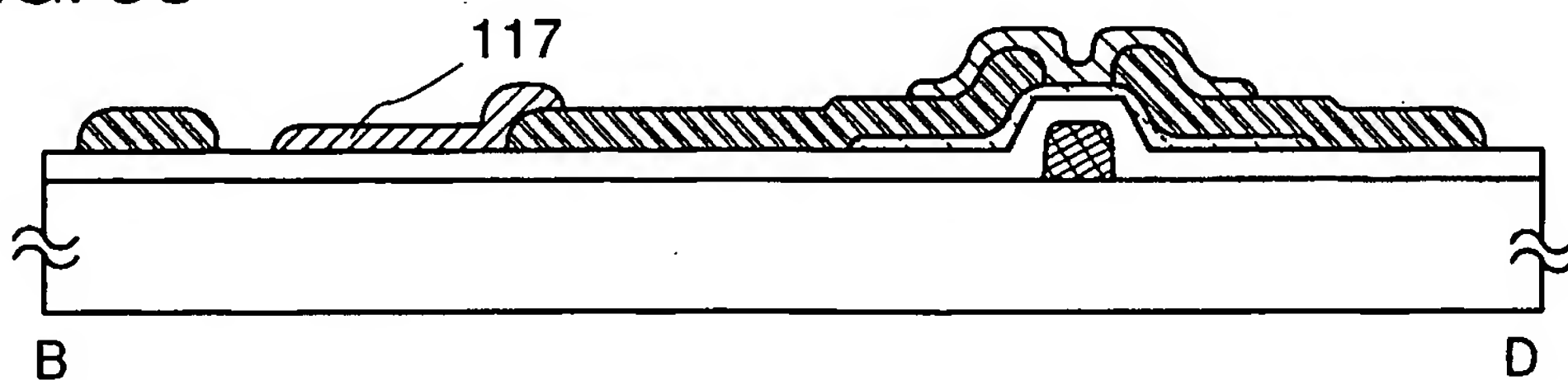


FIG. 9A

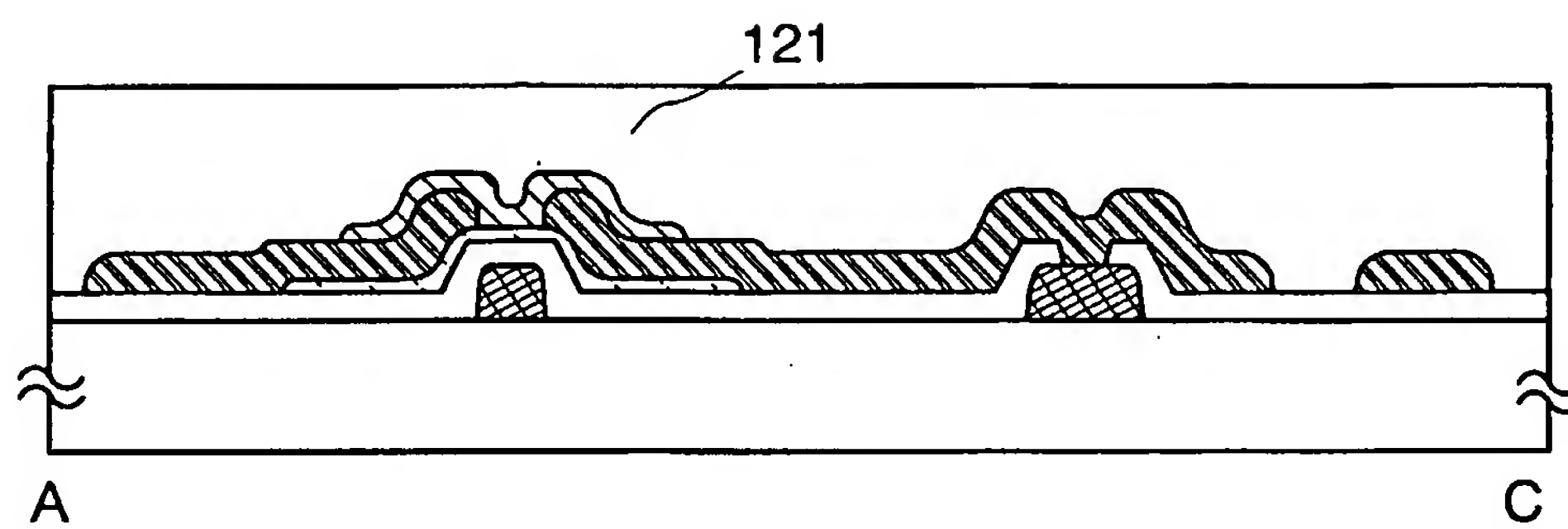


FIG. 9B

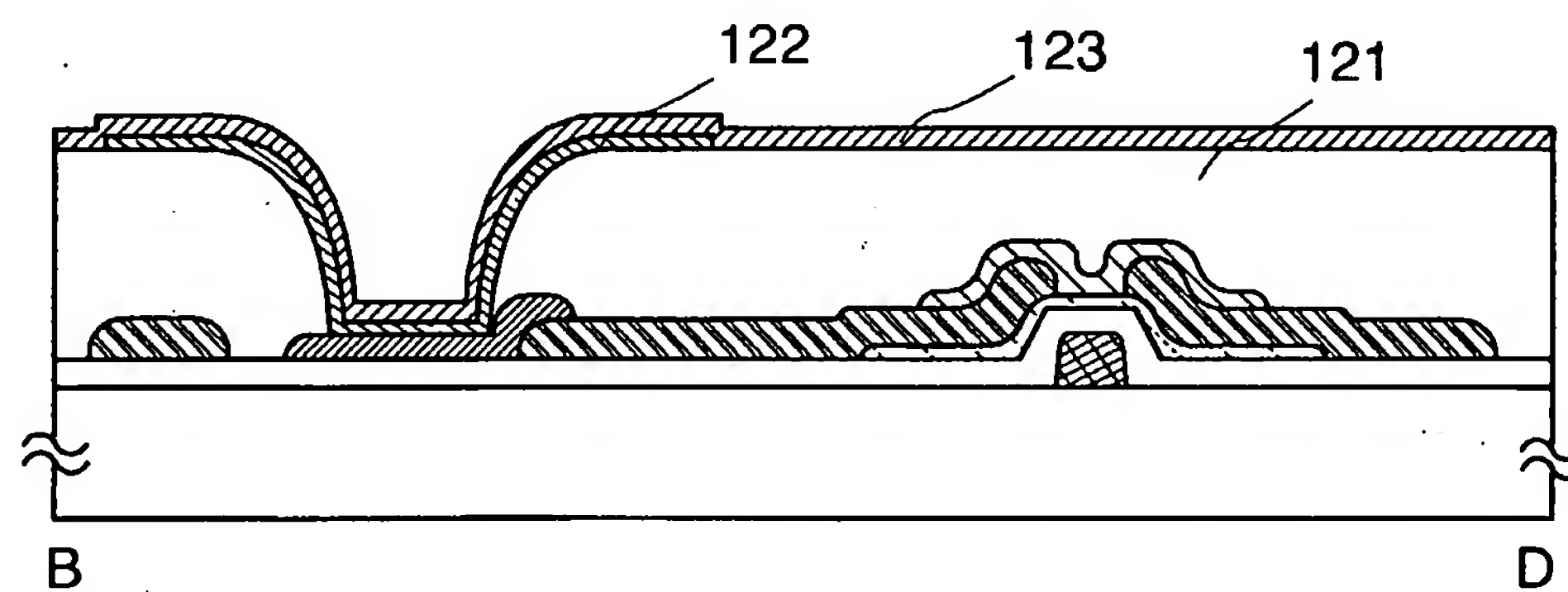


FIG. 10A

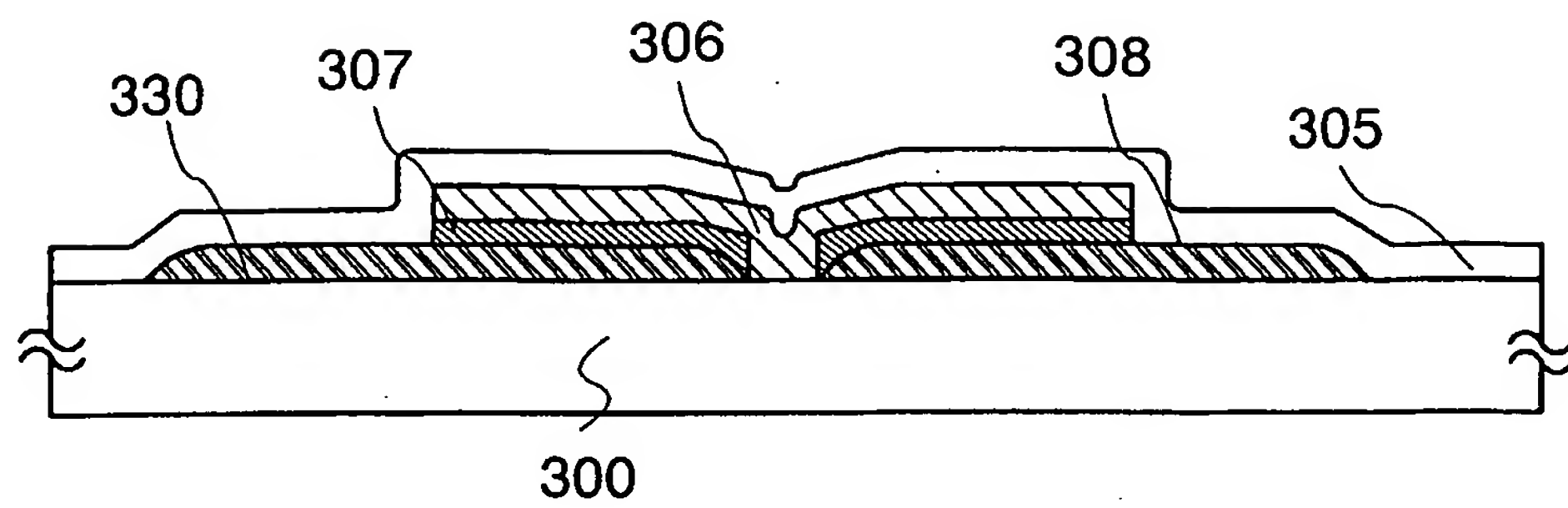


FIG. 10B

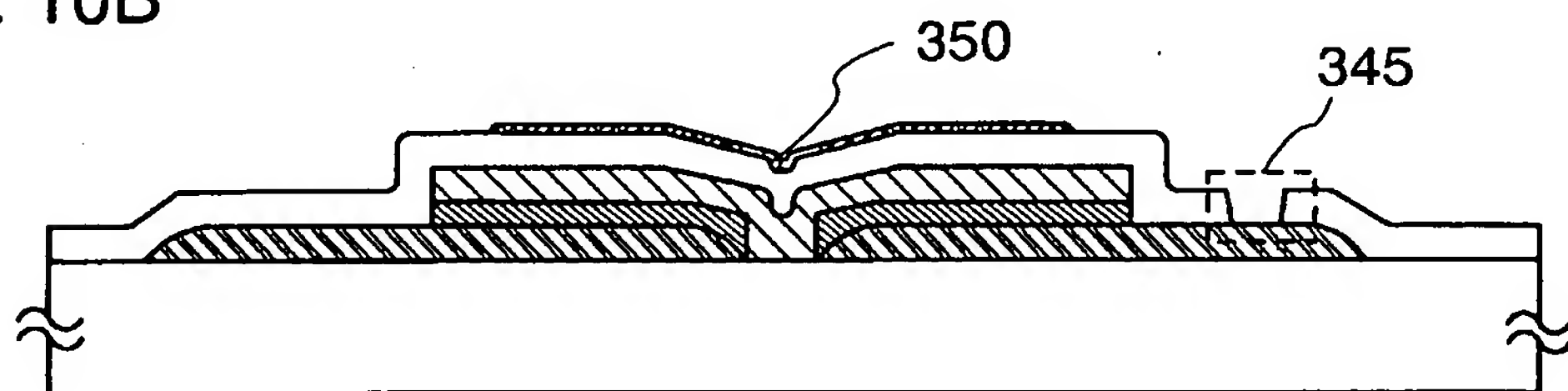


FIG. 10C

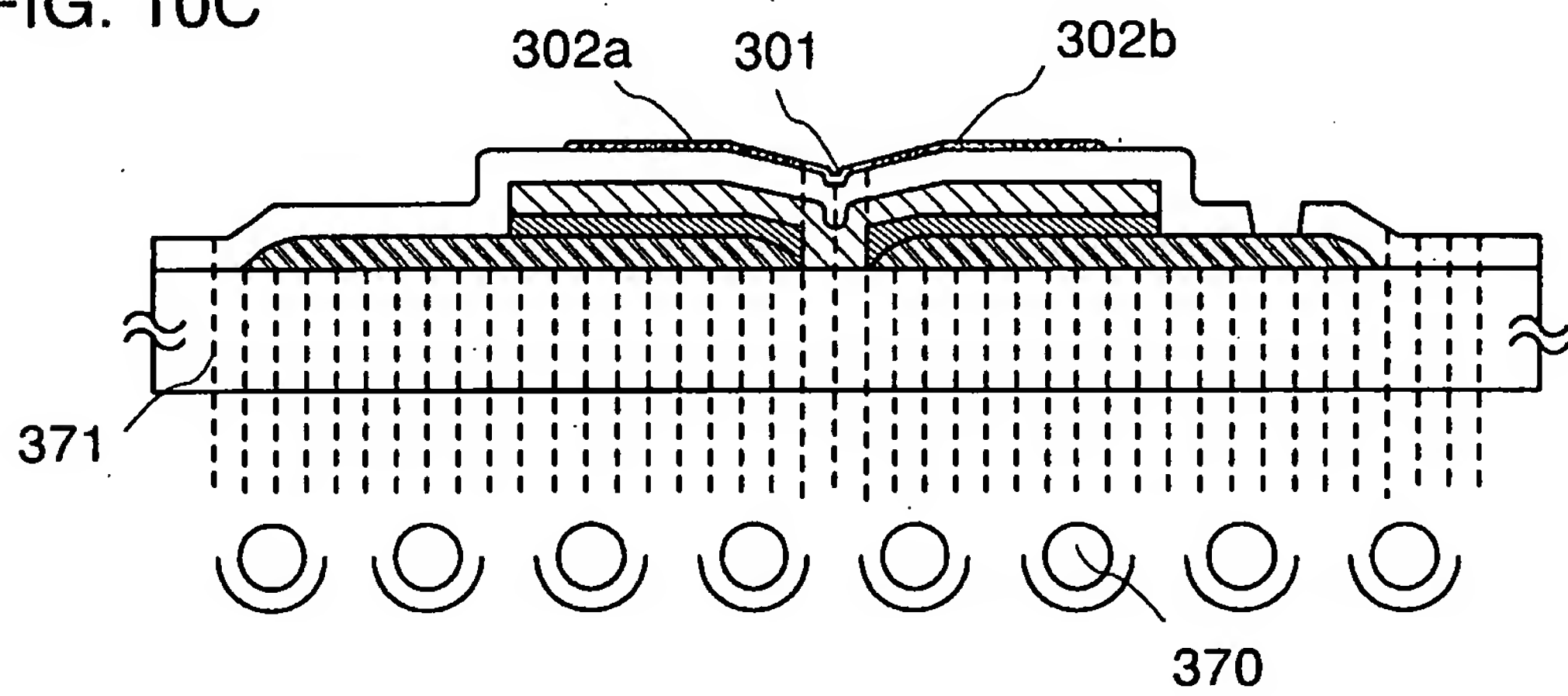


FIG. 11A

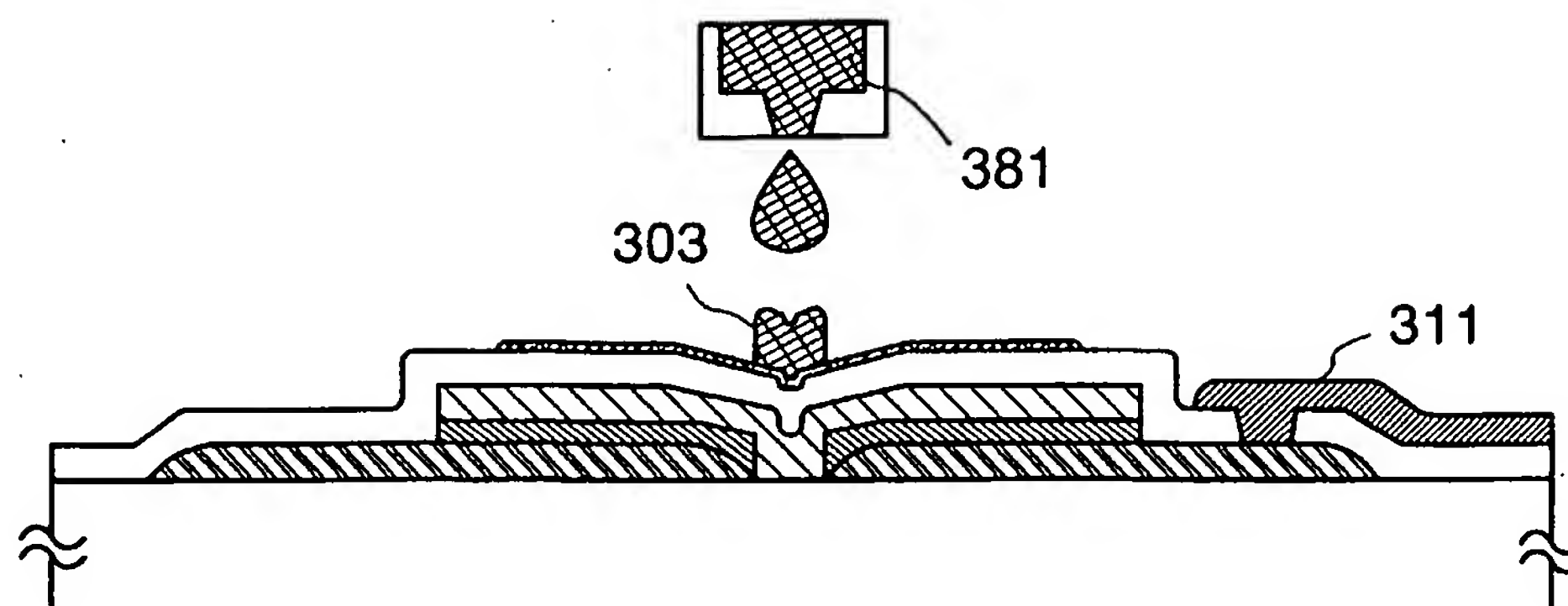


FIG. 11B

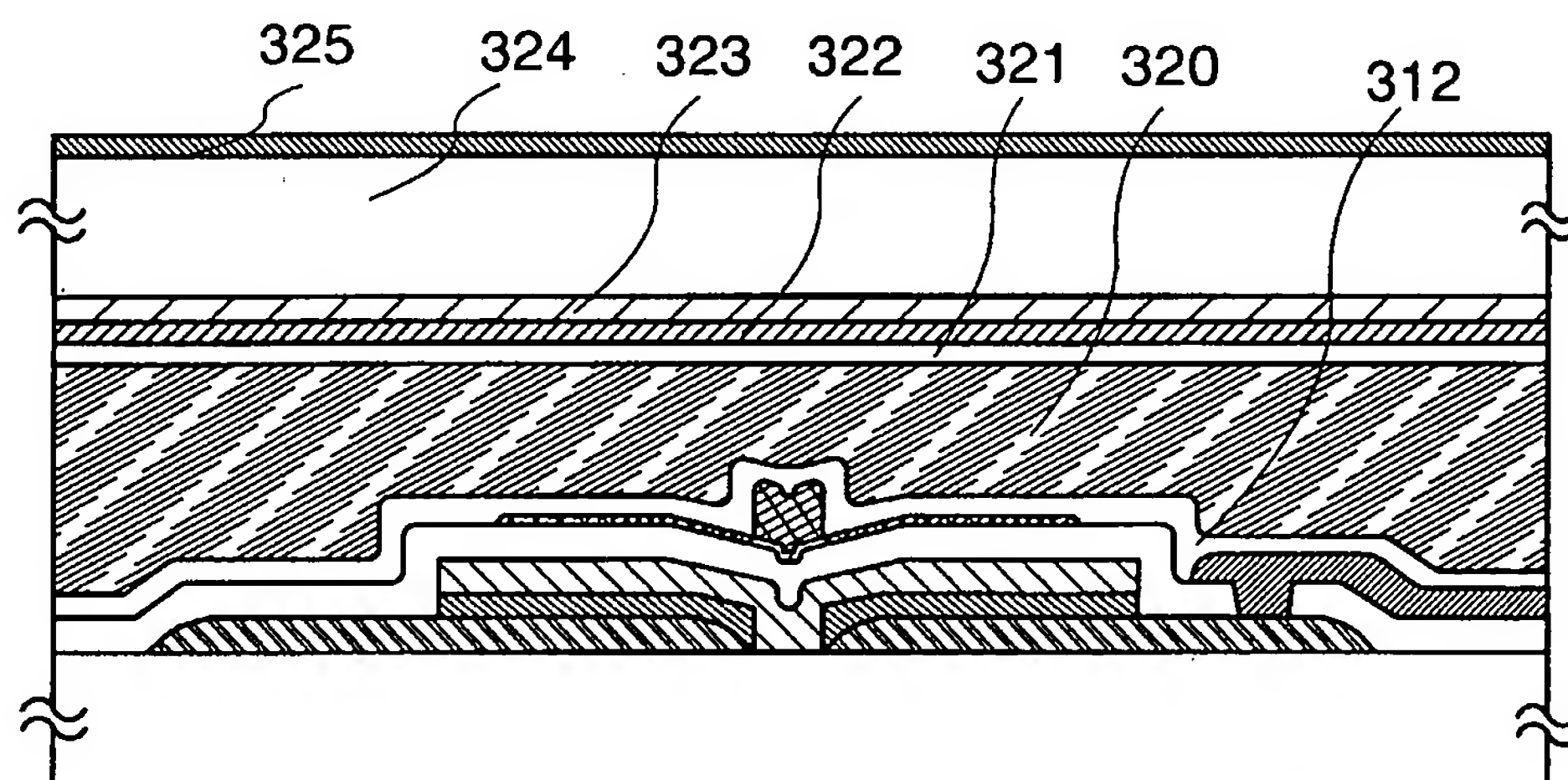


FIG. 12A

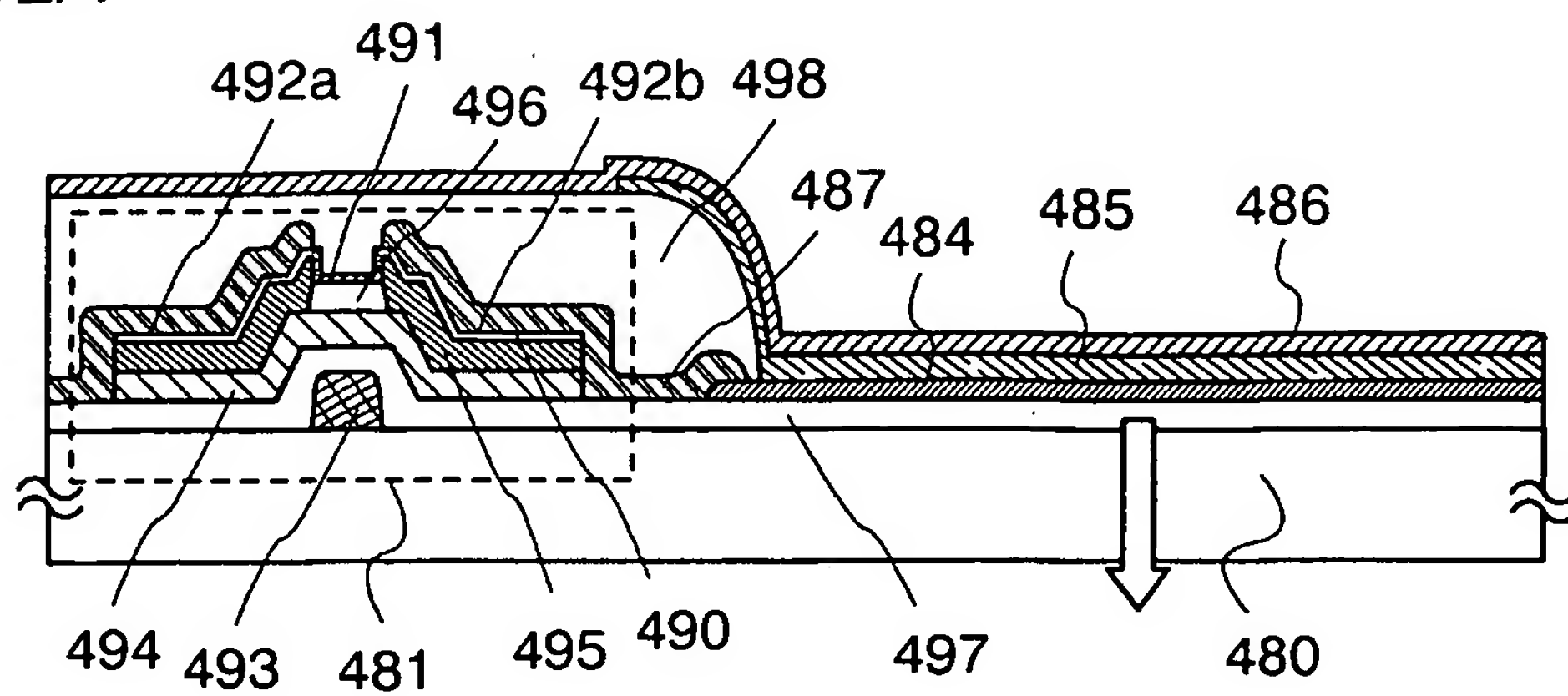


FIG. 12B

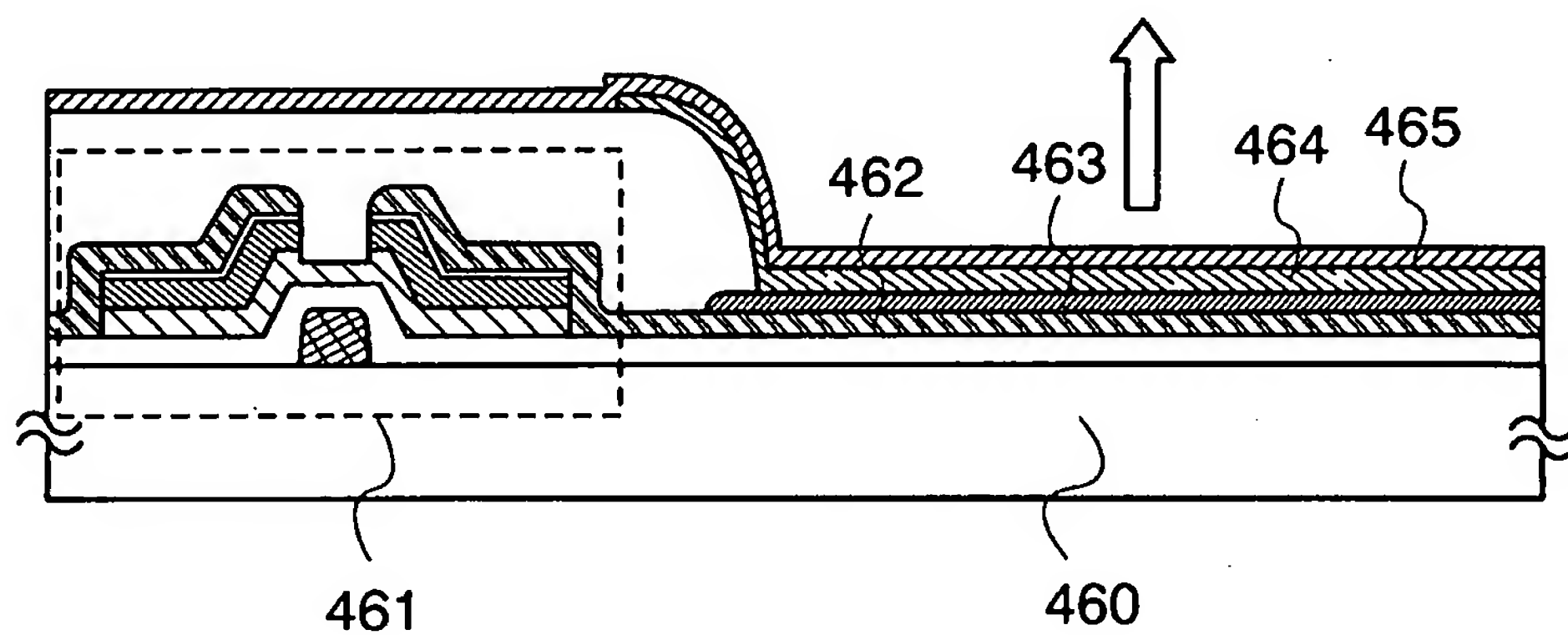


FIG. 12C

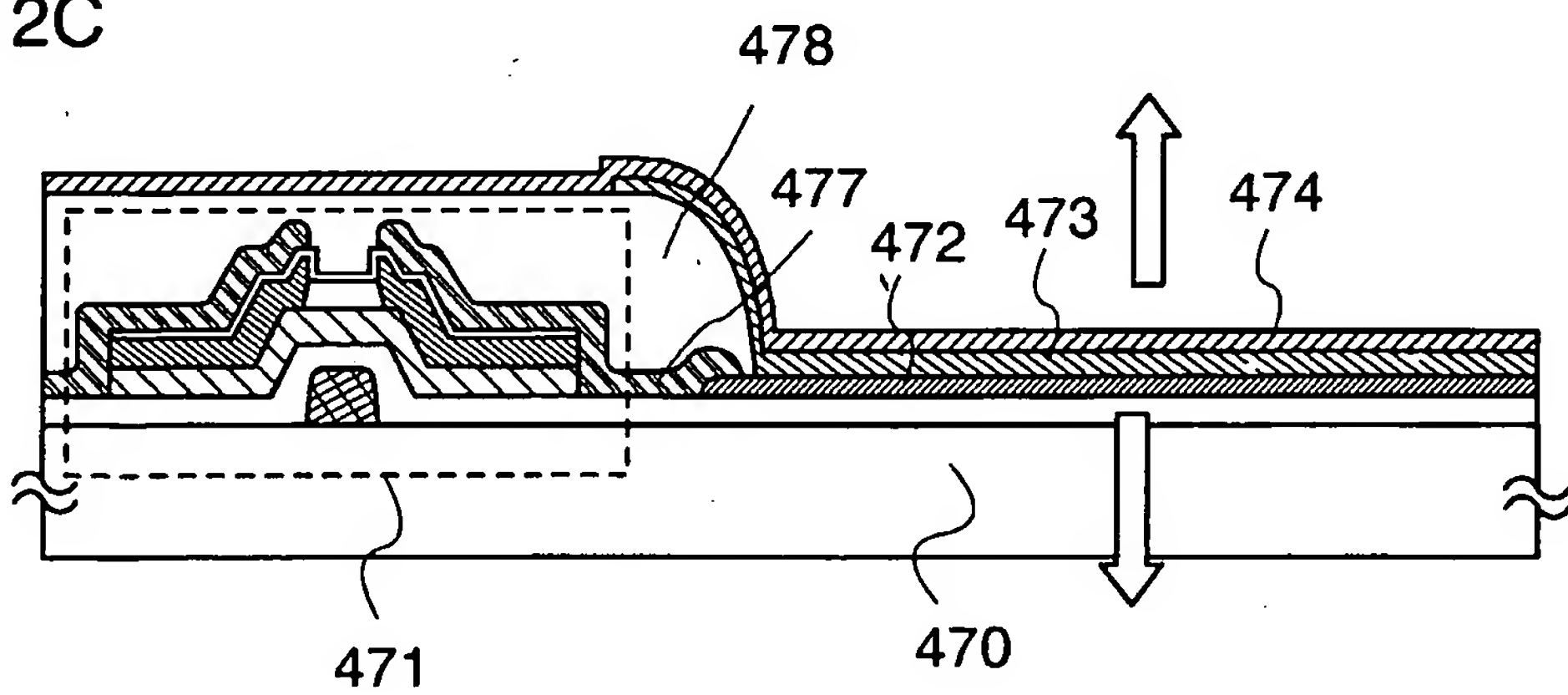


FIG. 13

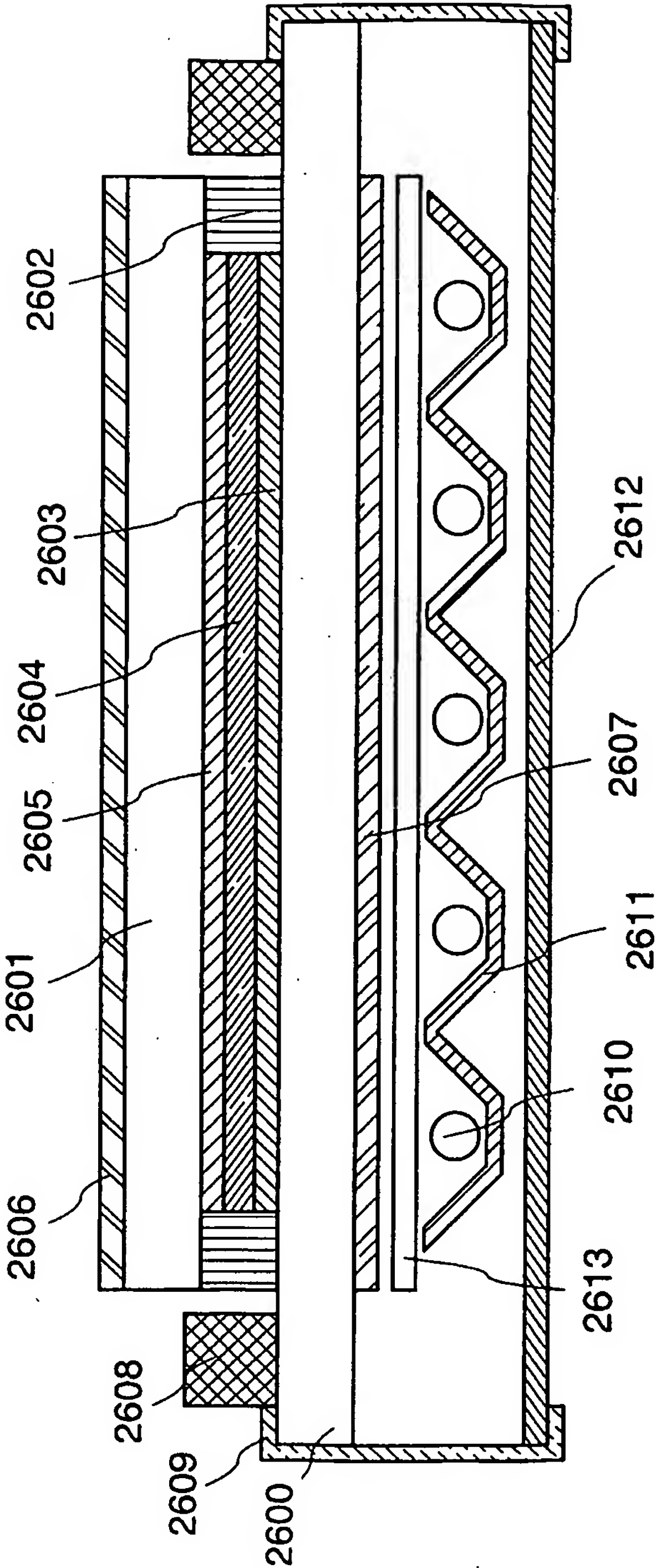


FIG. 14A

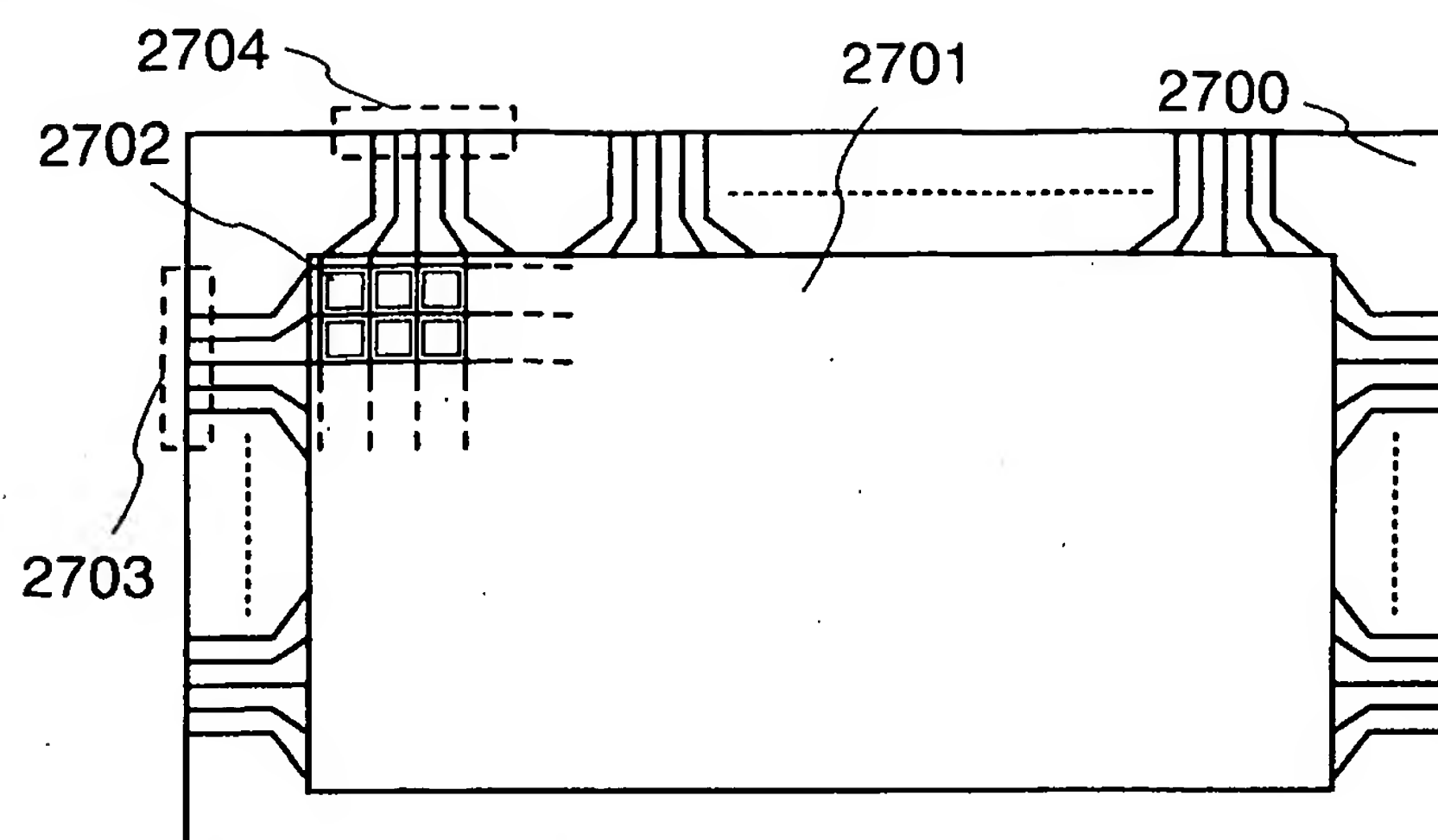


FIG. 14B

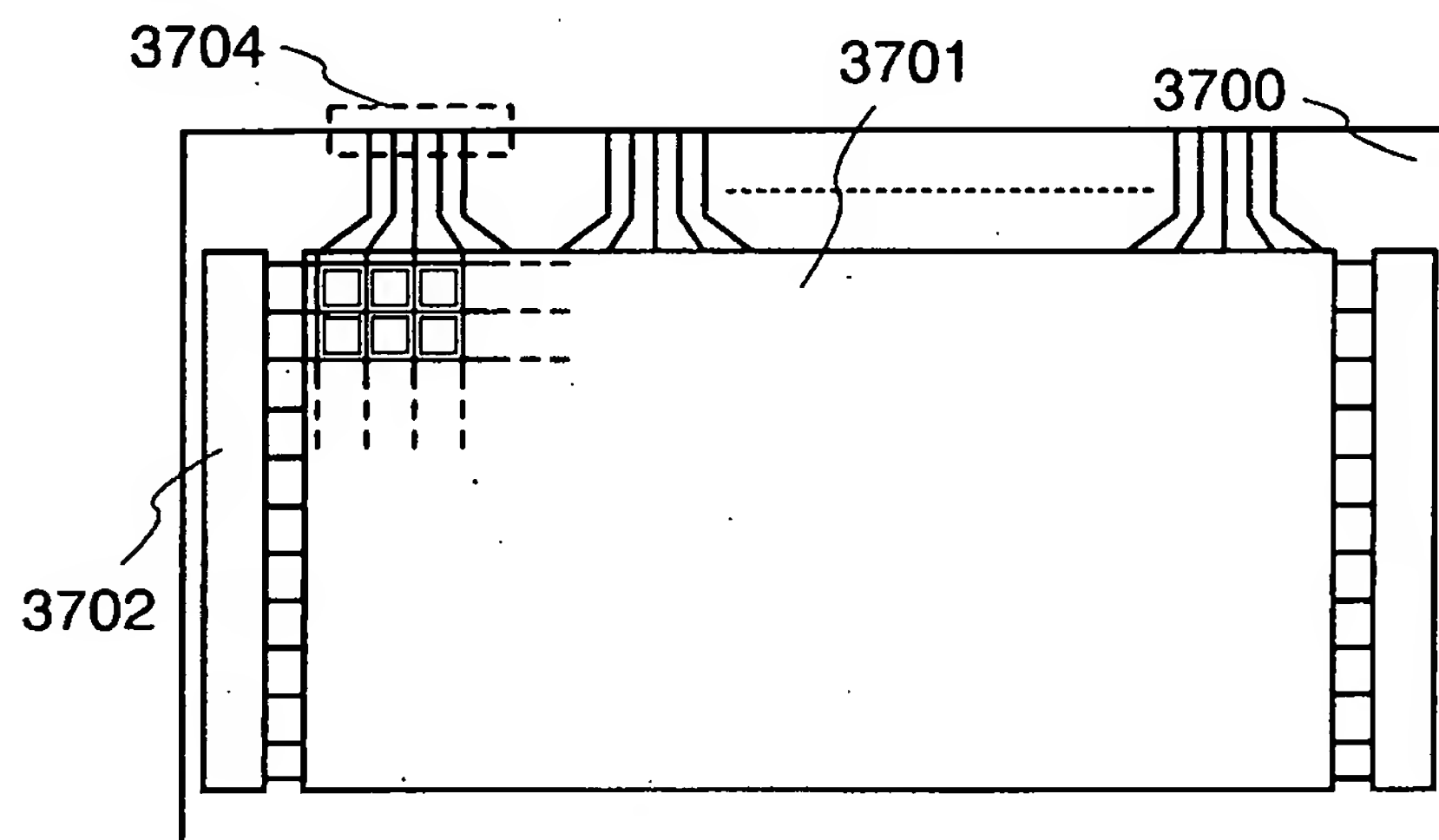


FIG. 14C

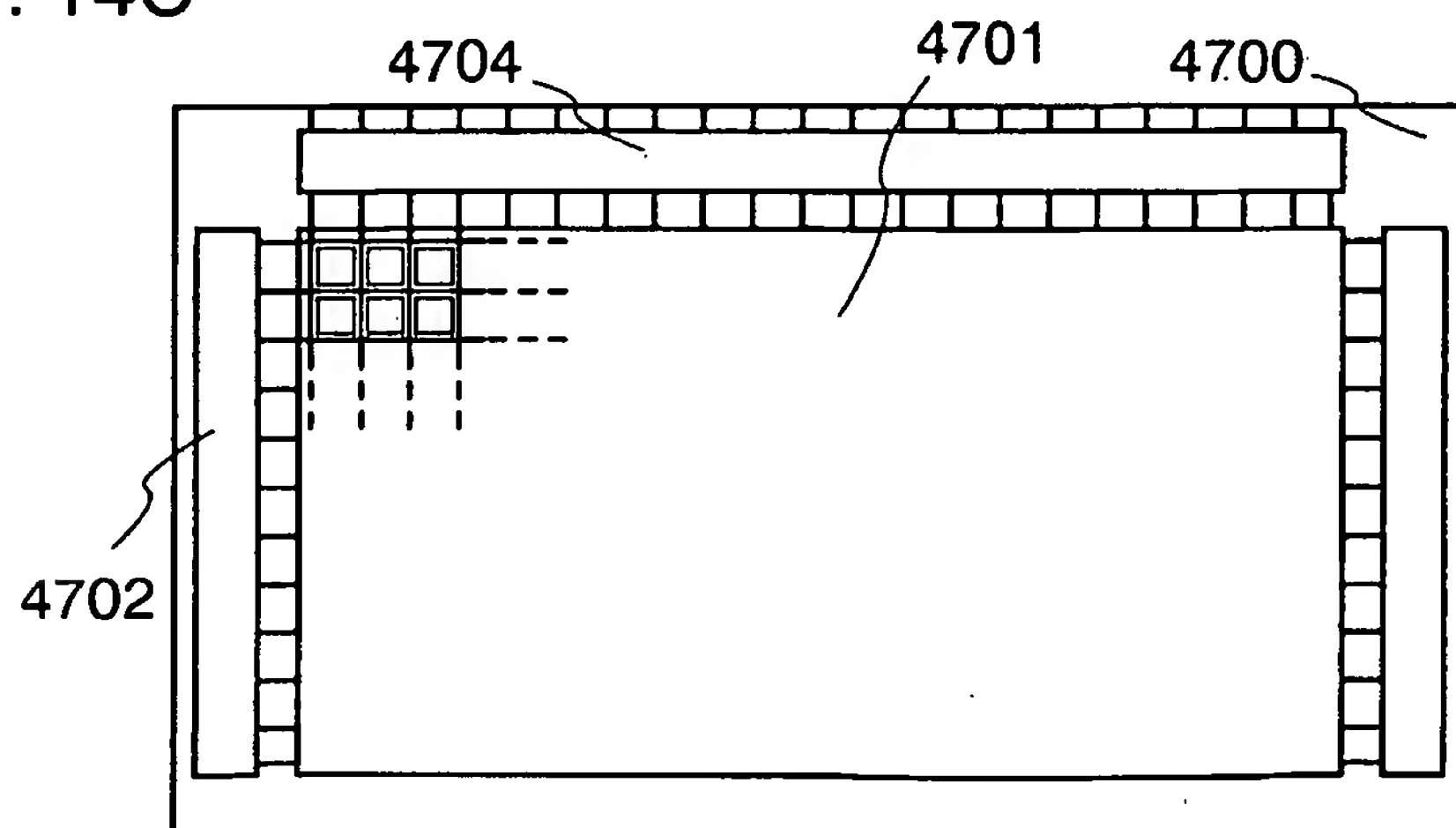


FIG. 15A

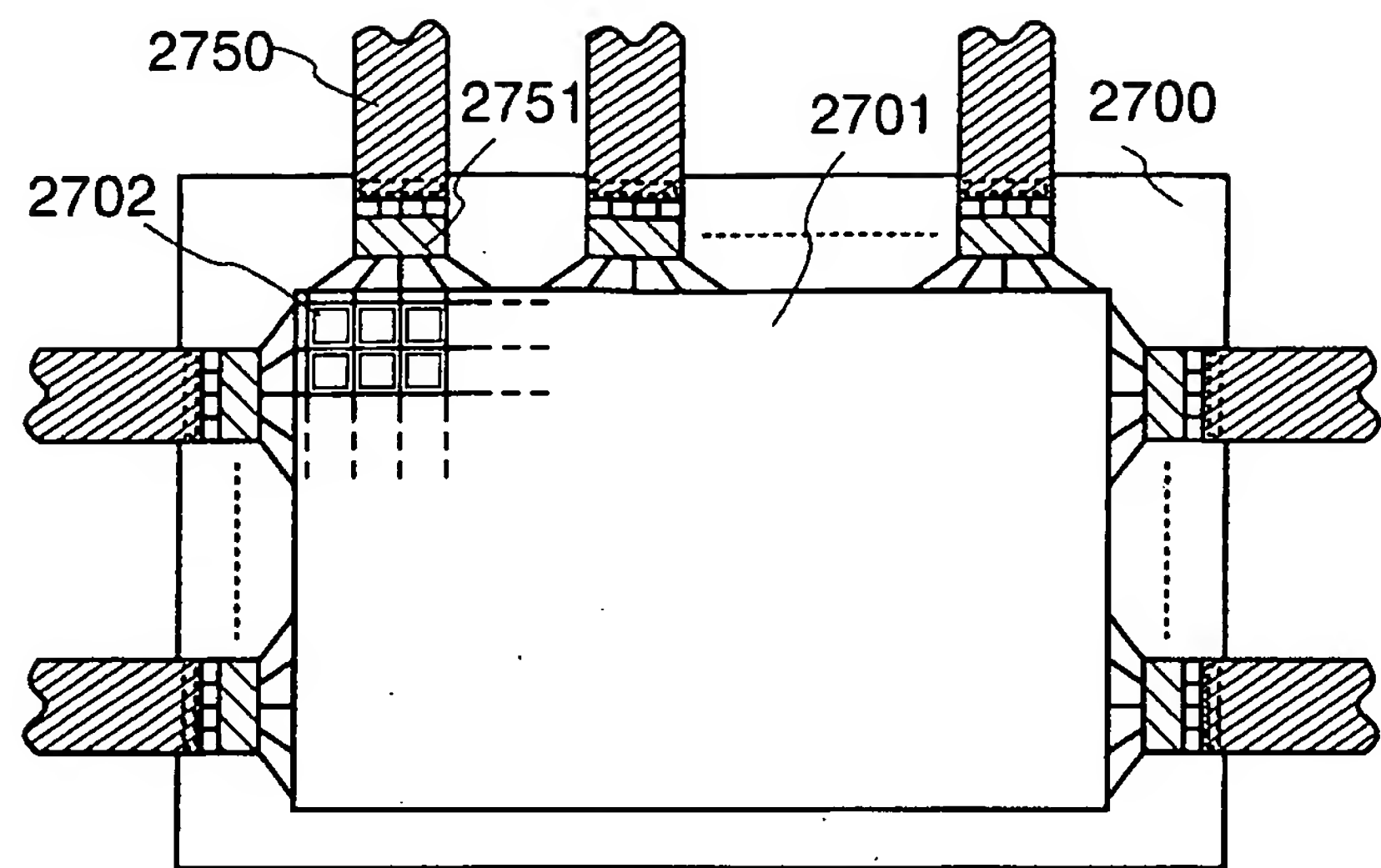


FIG. 15B

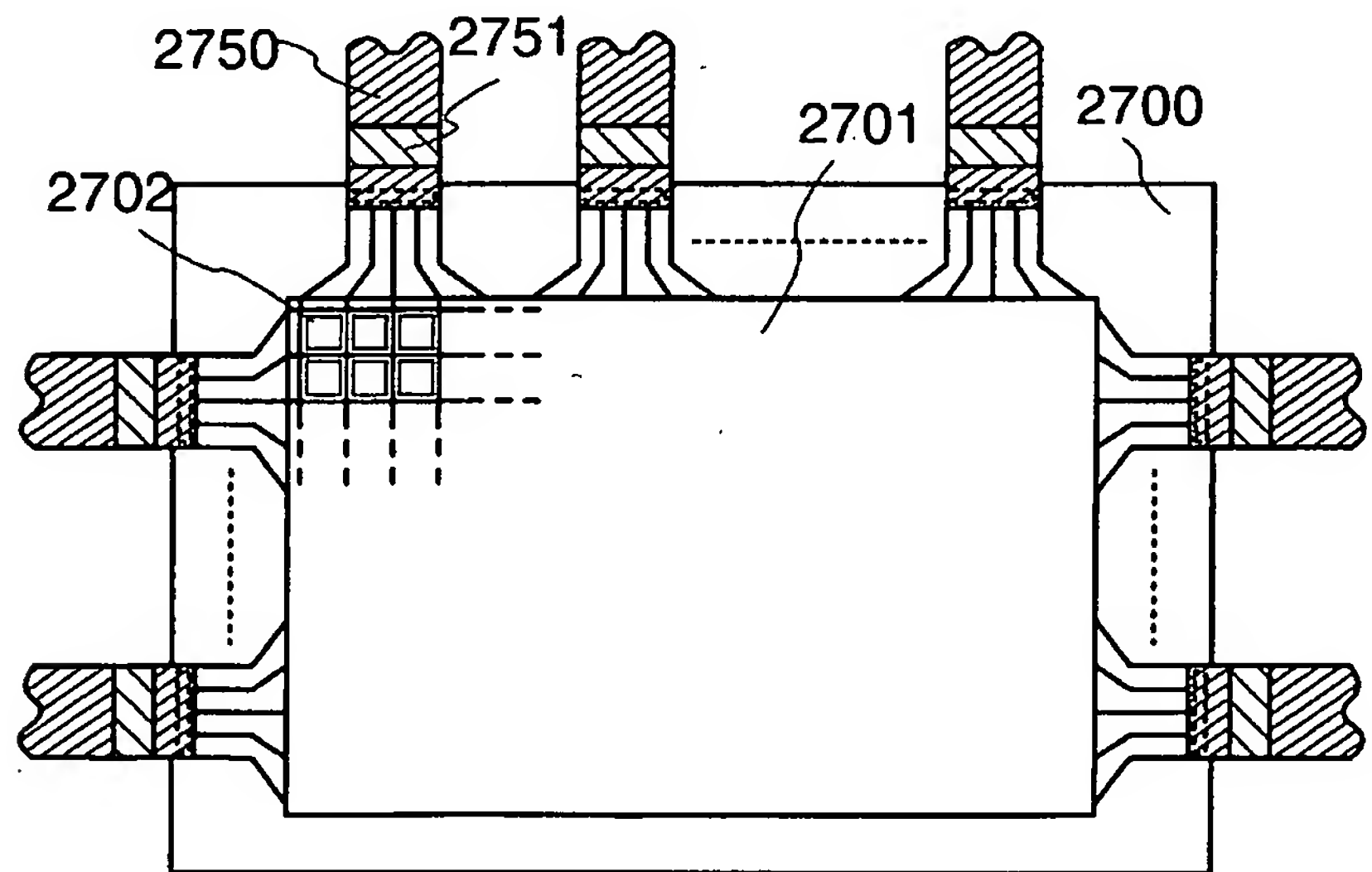


FIG. 16

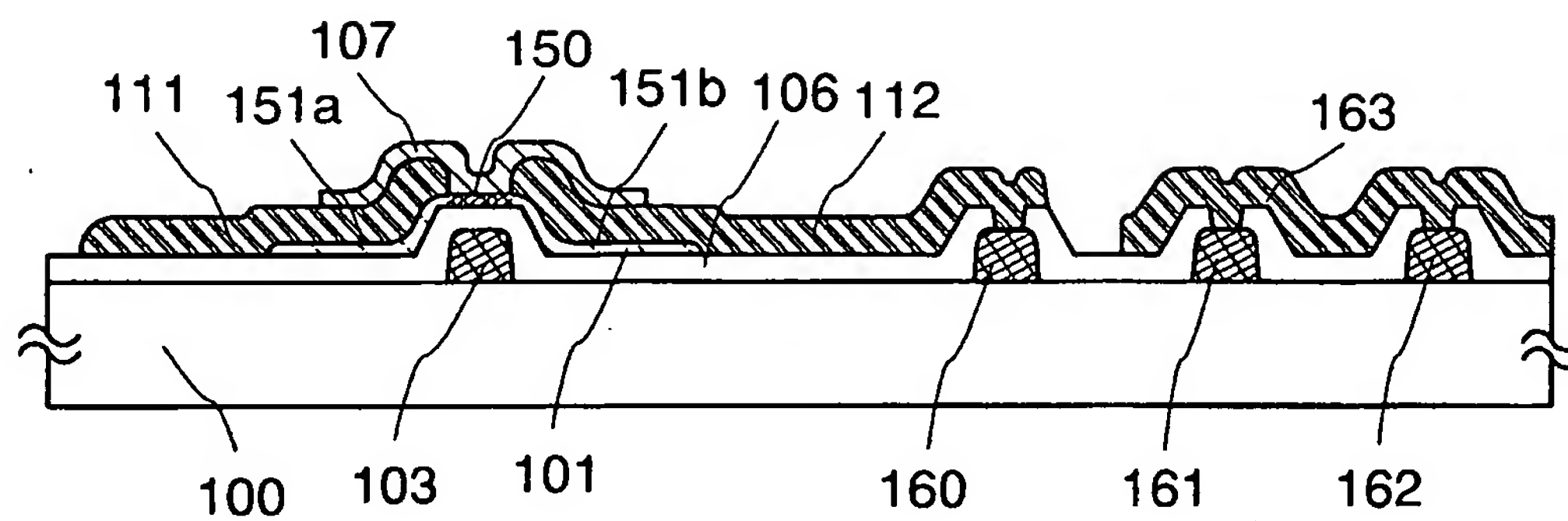


FIG. 17A

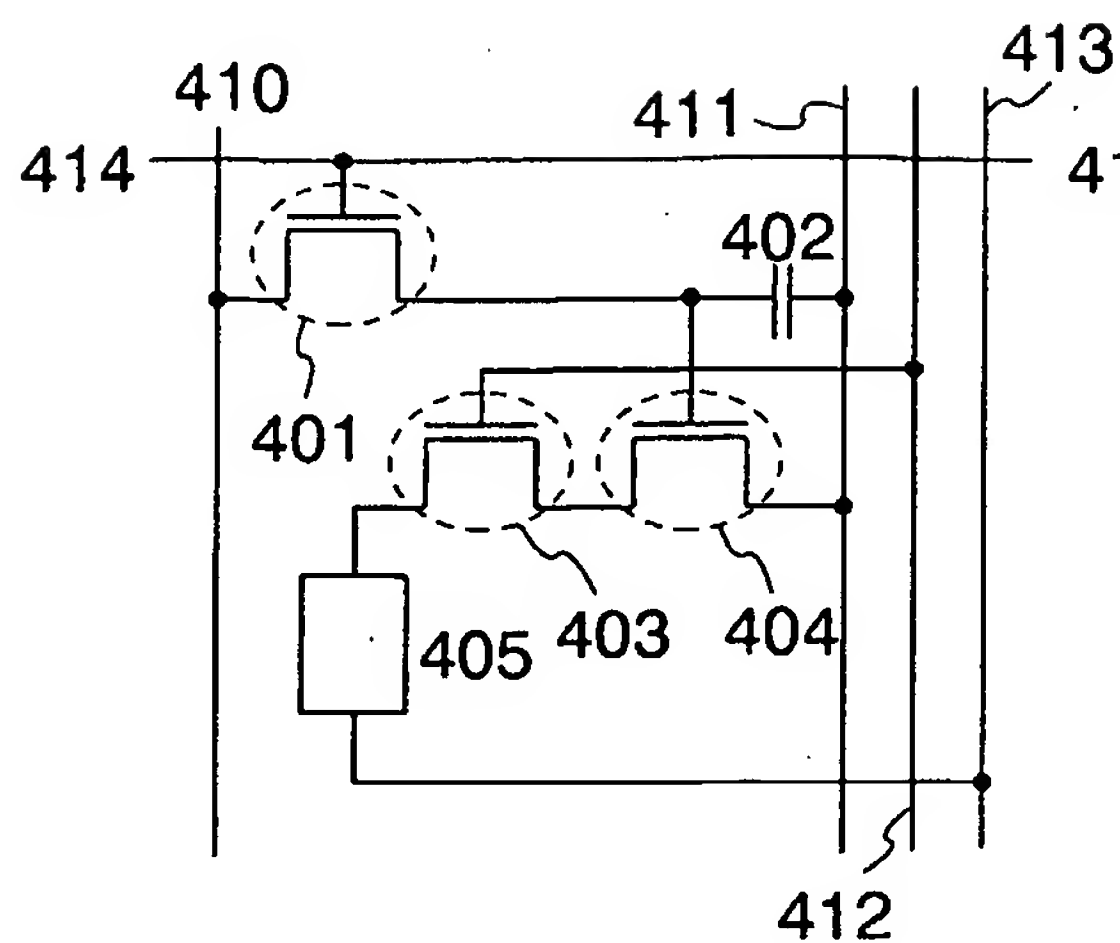


FIG. 17B

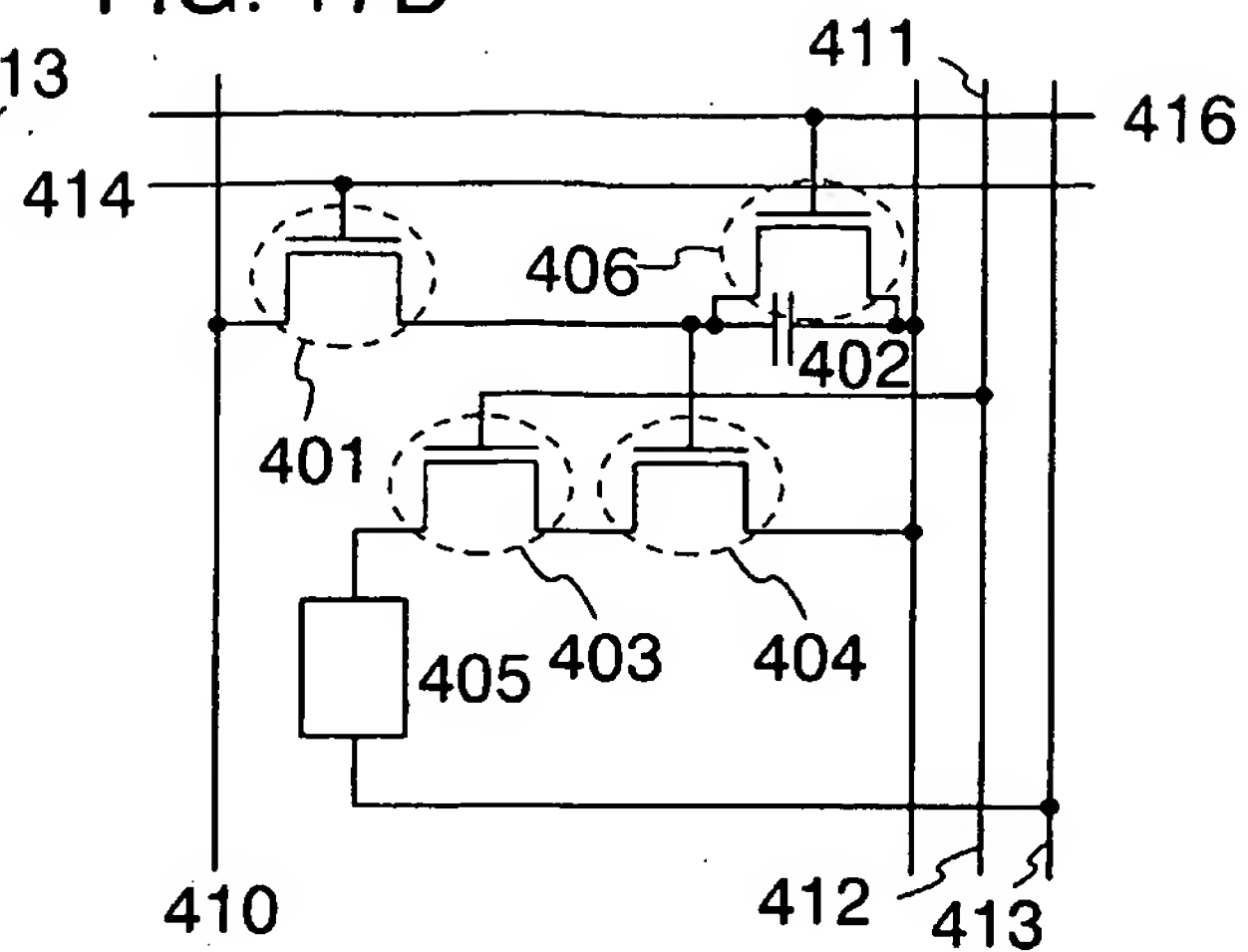


FIG. 17C

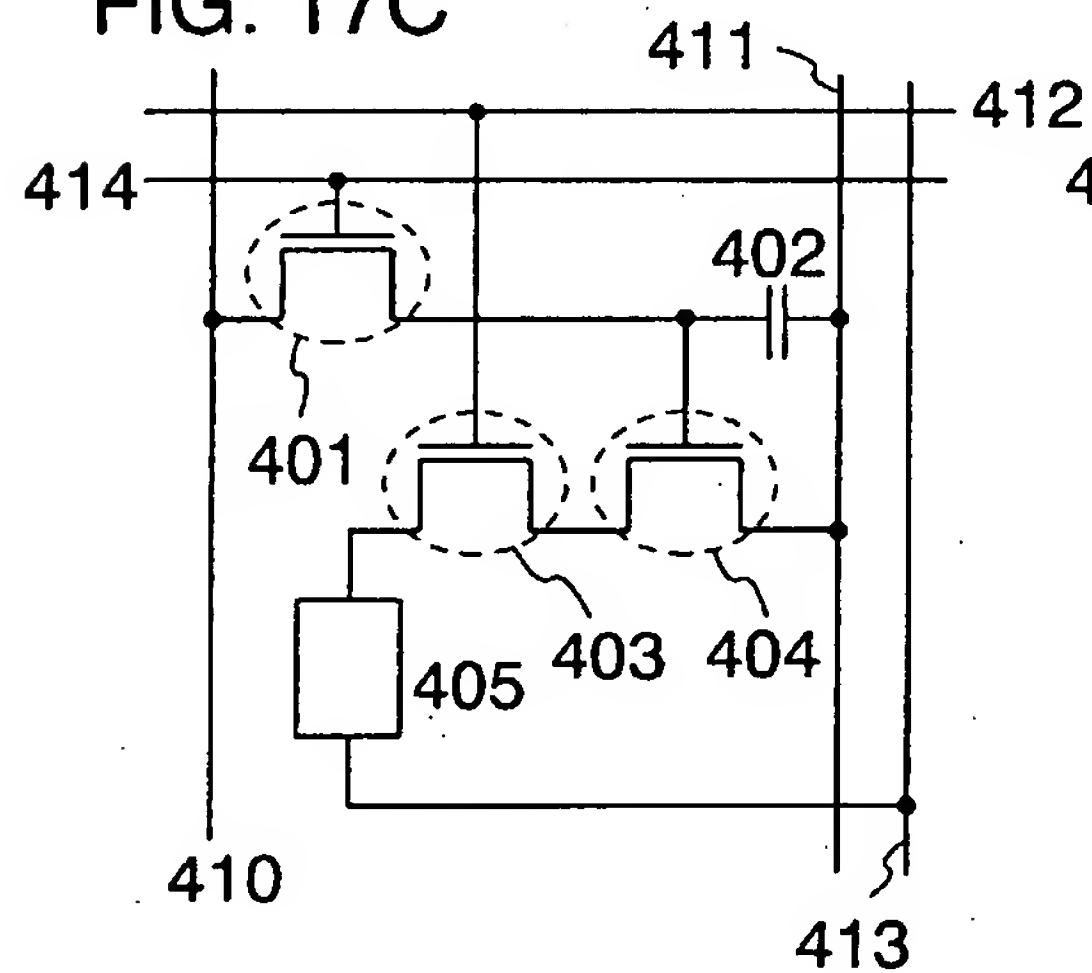


FIG. 17D

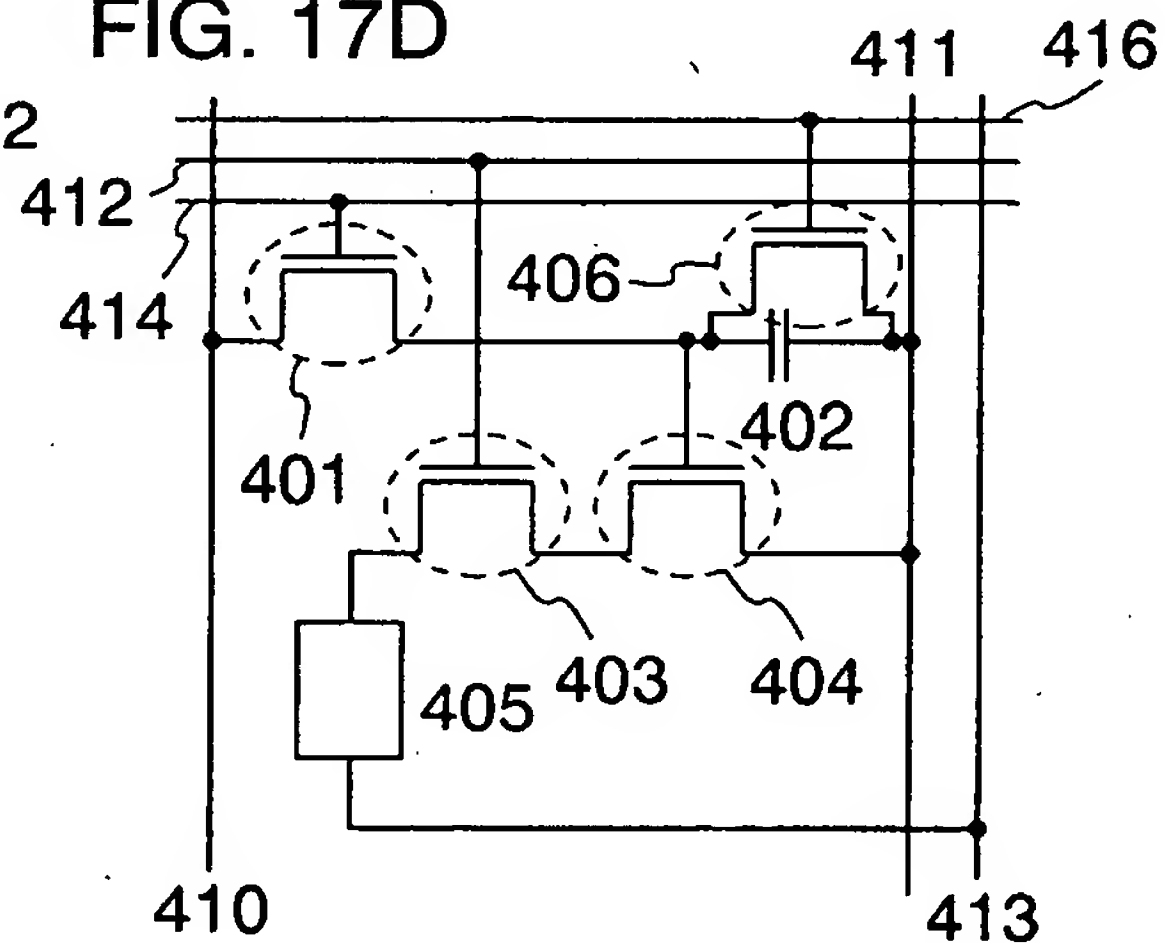


FIG. 17E

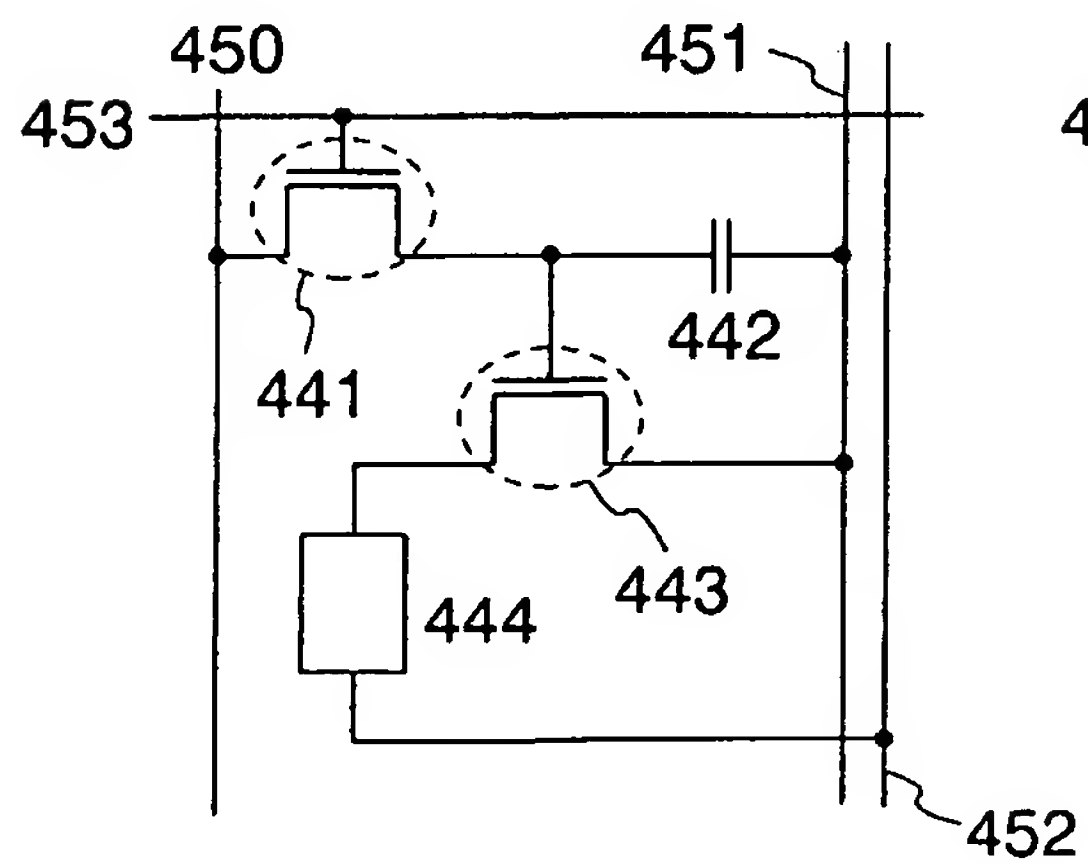


FIG. 17F

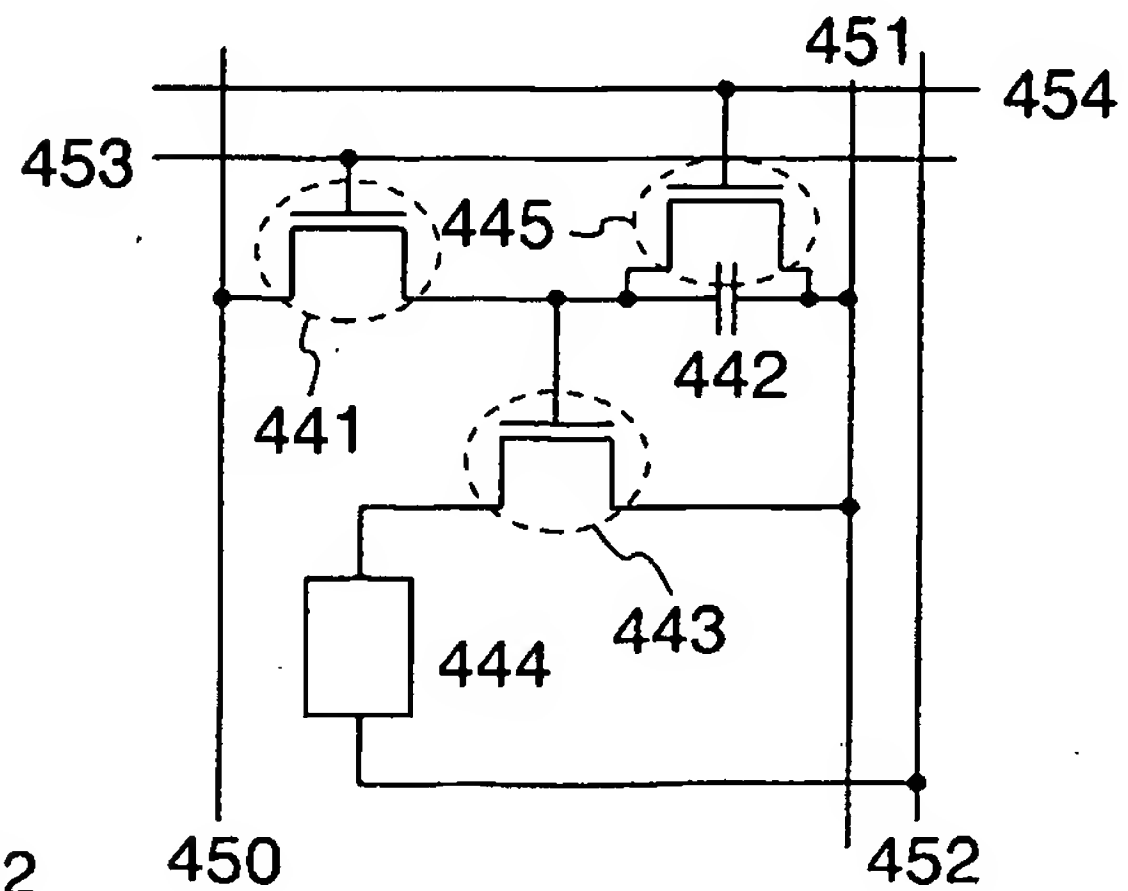


FIG. 18A

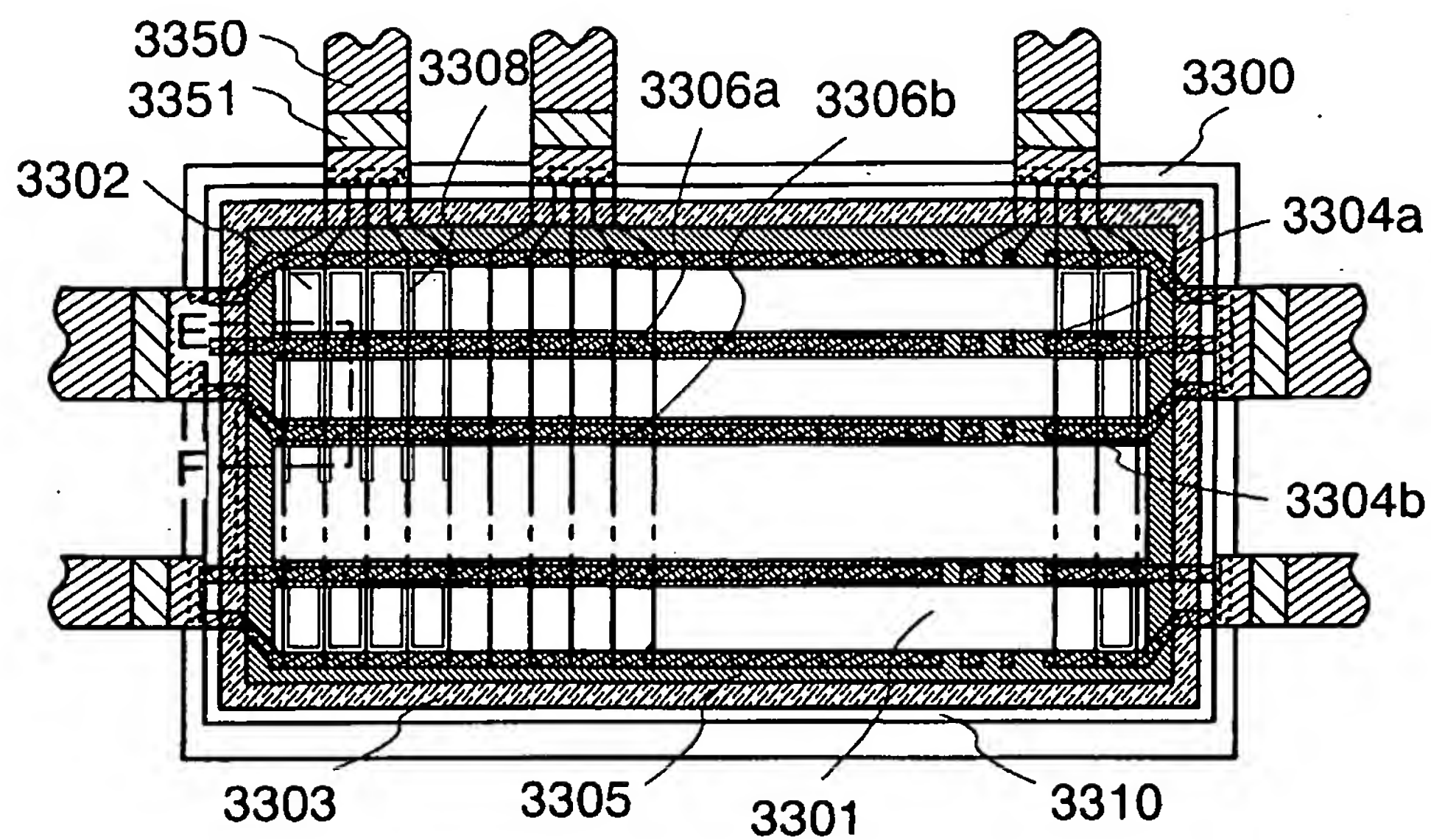


FIG. 18B

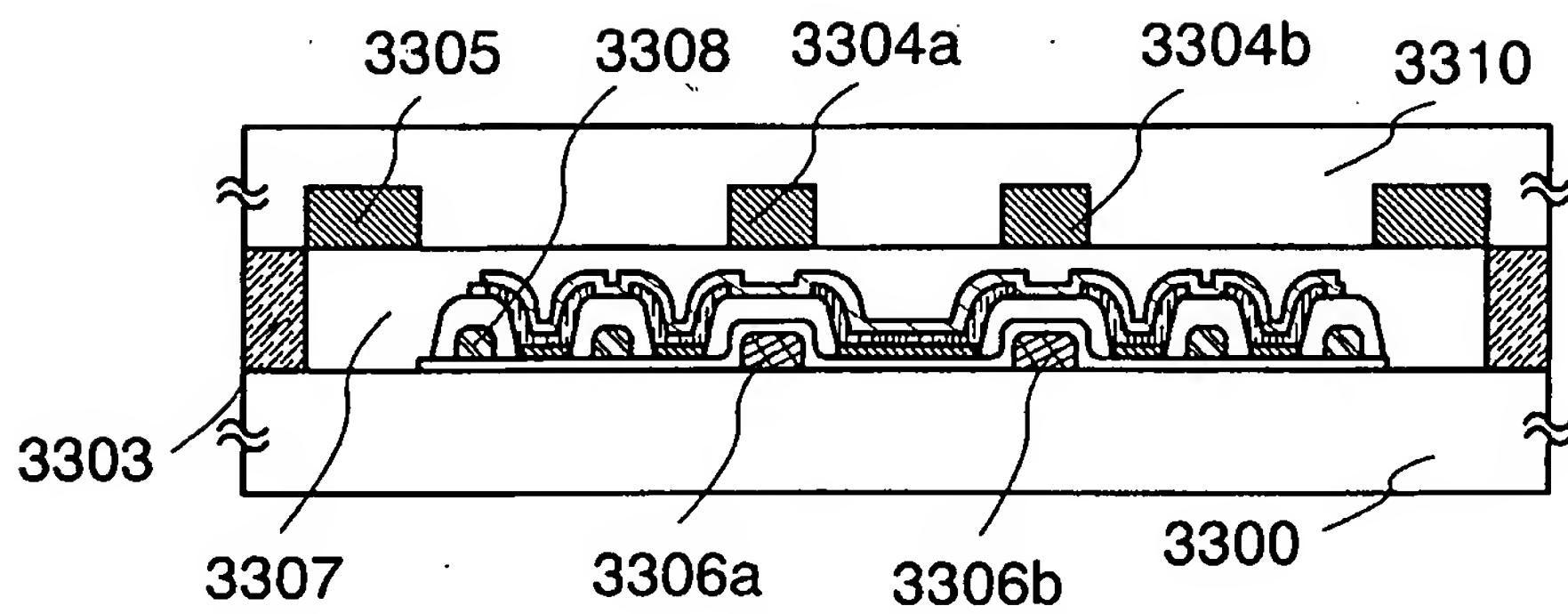


FIG. 19

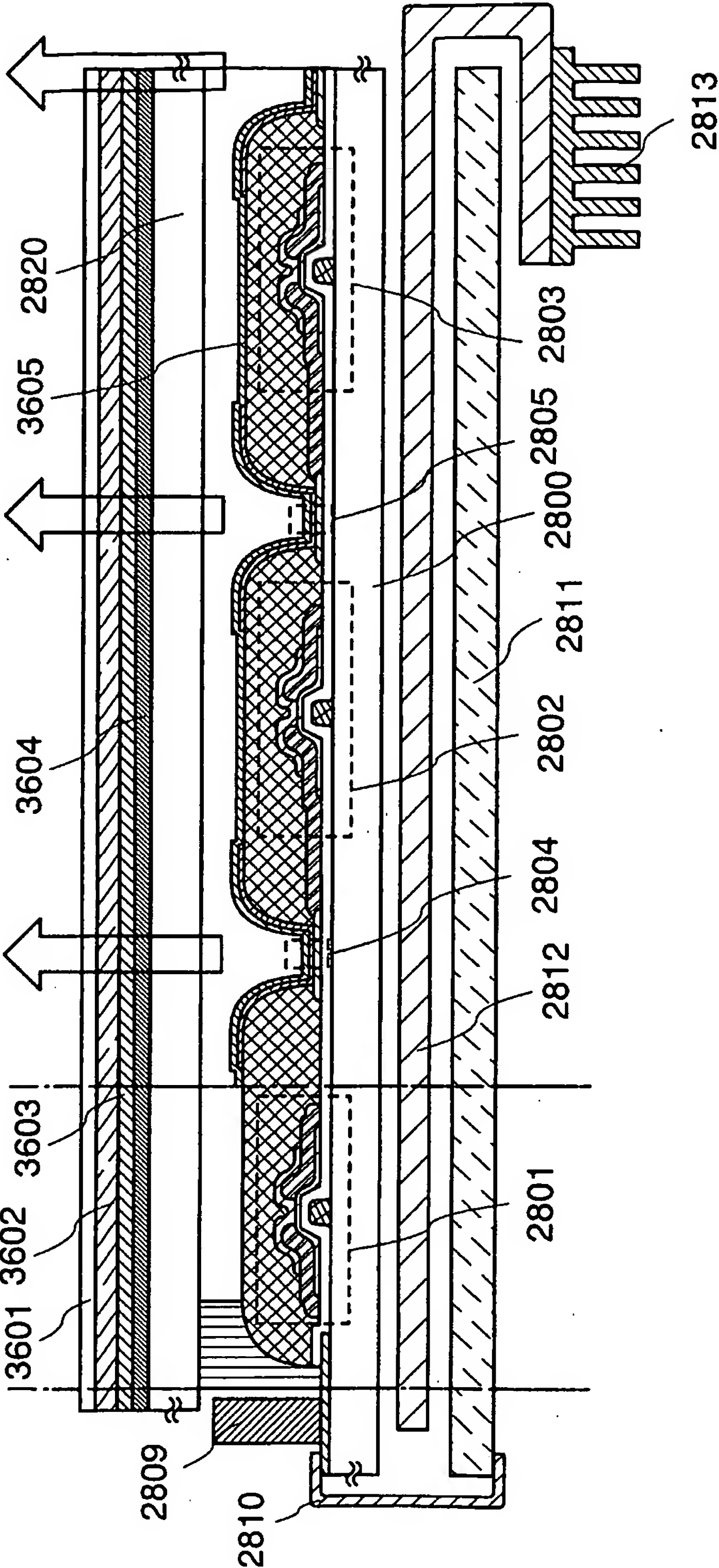


FIG. 20A

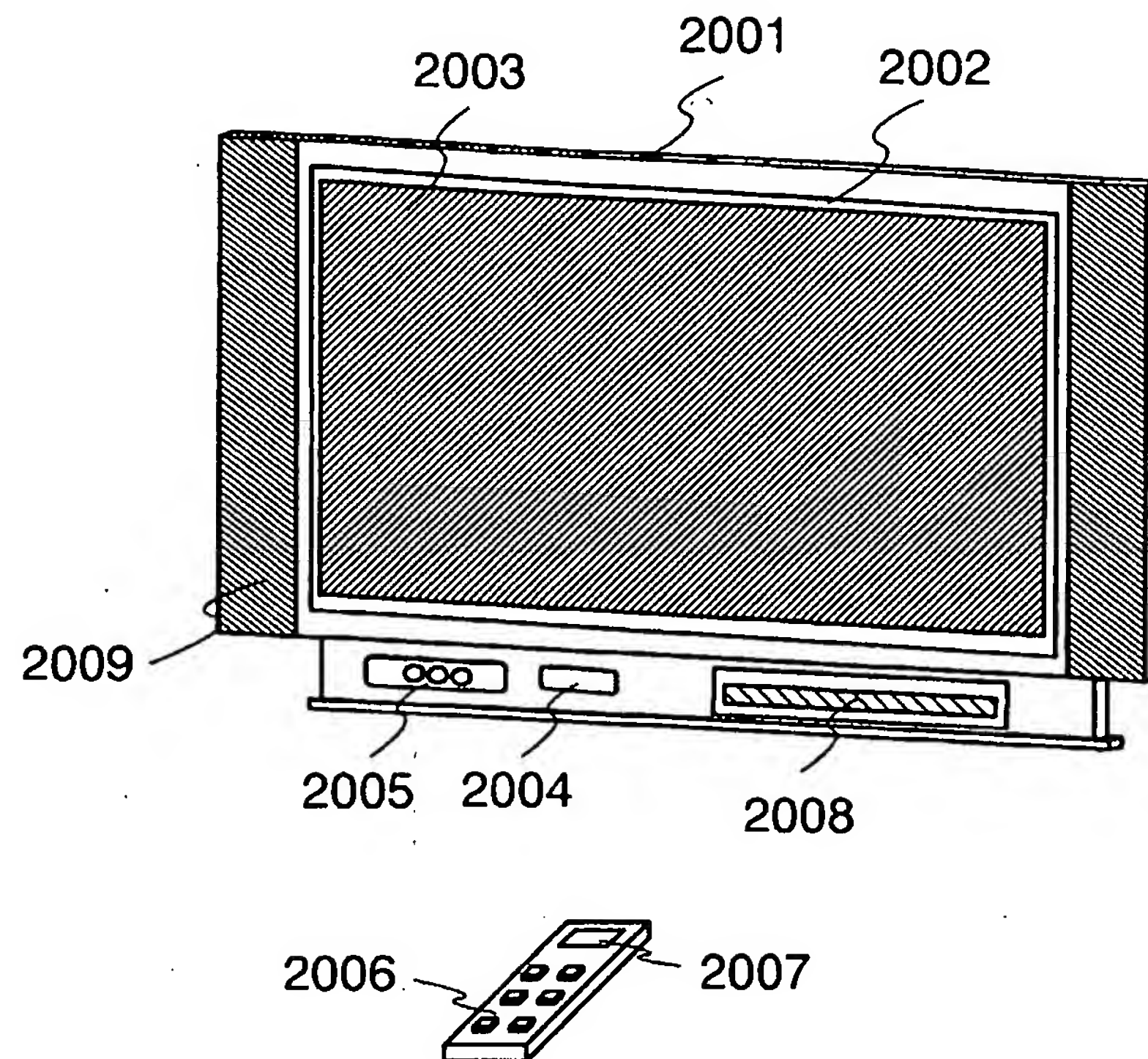


FIG. 20B

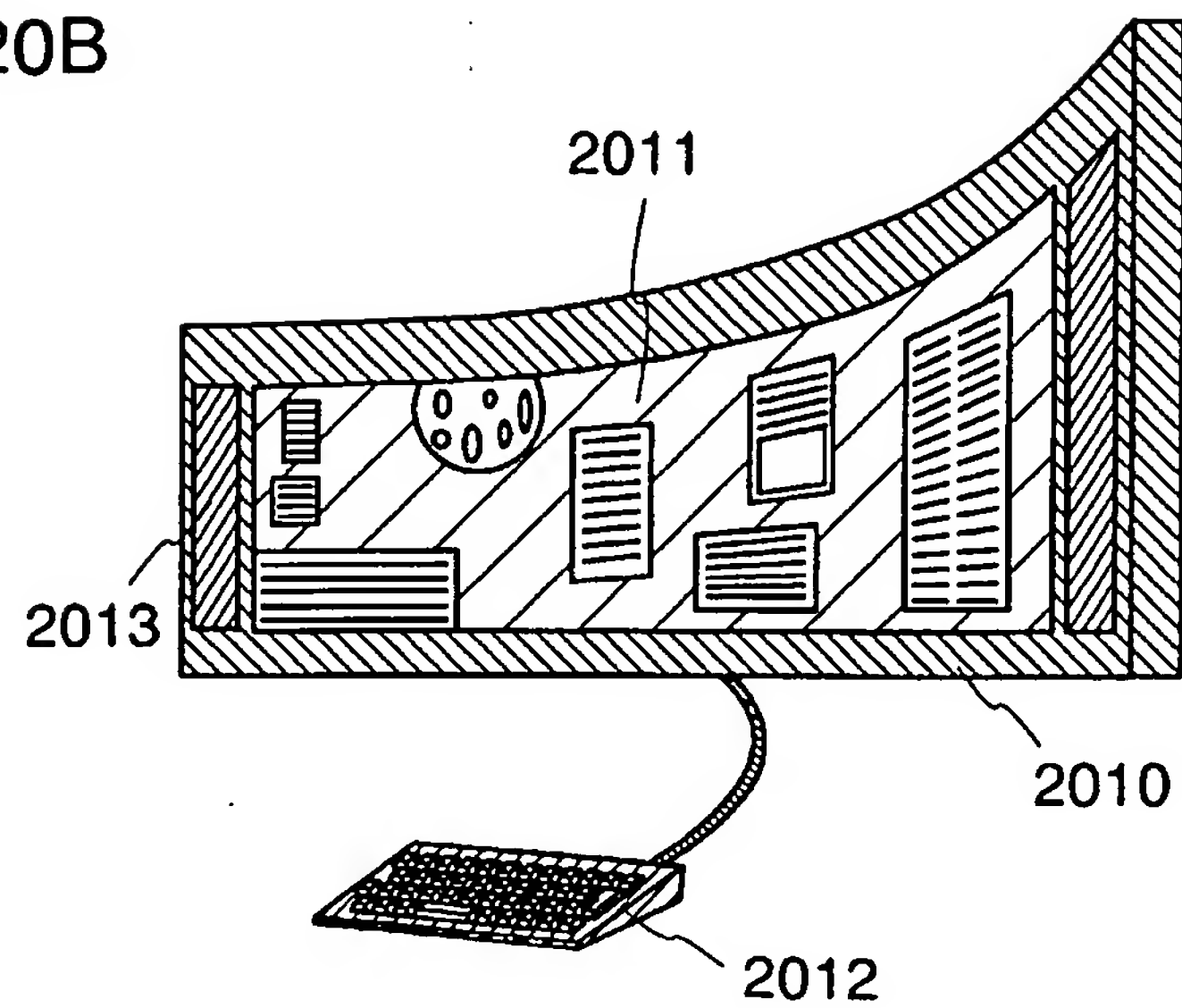


FIG. 21A

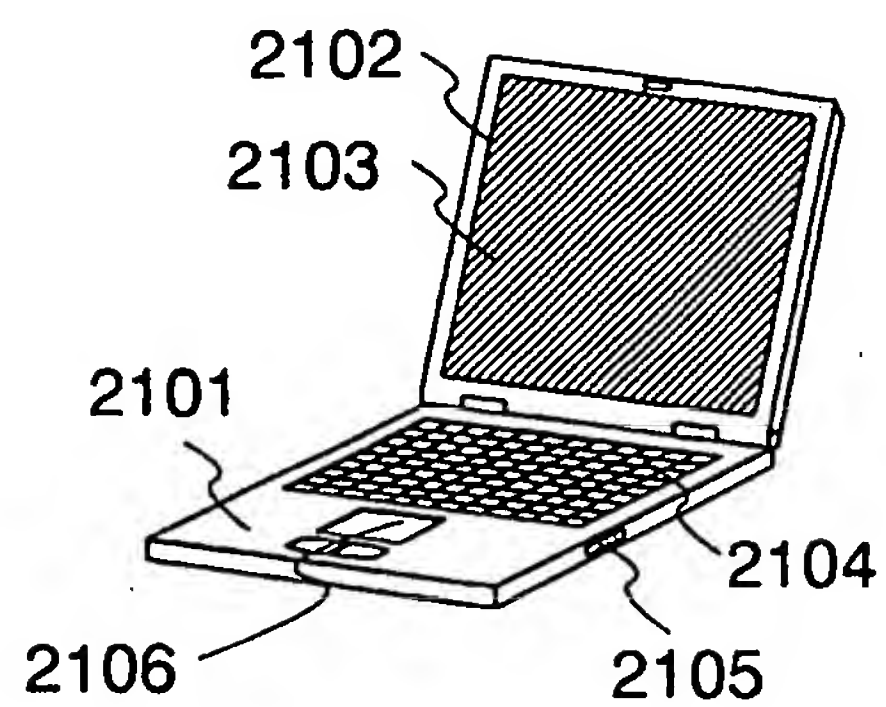


FIG. 21B

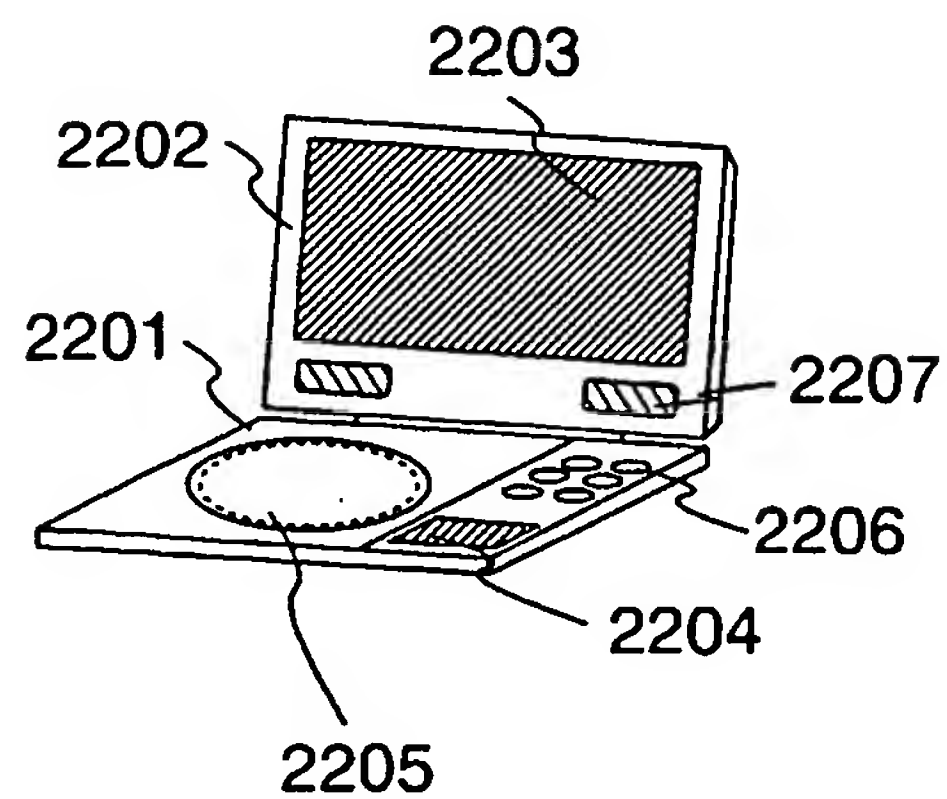


FIG. 21C

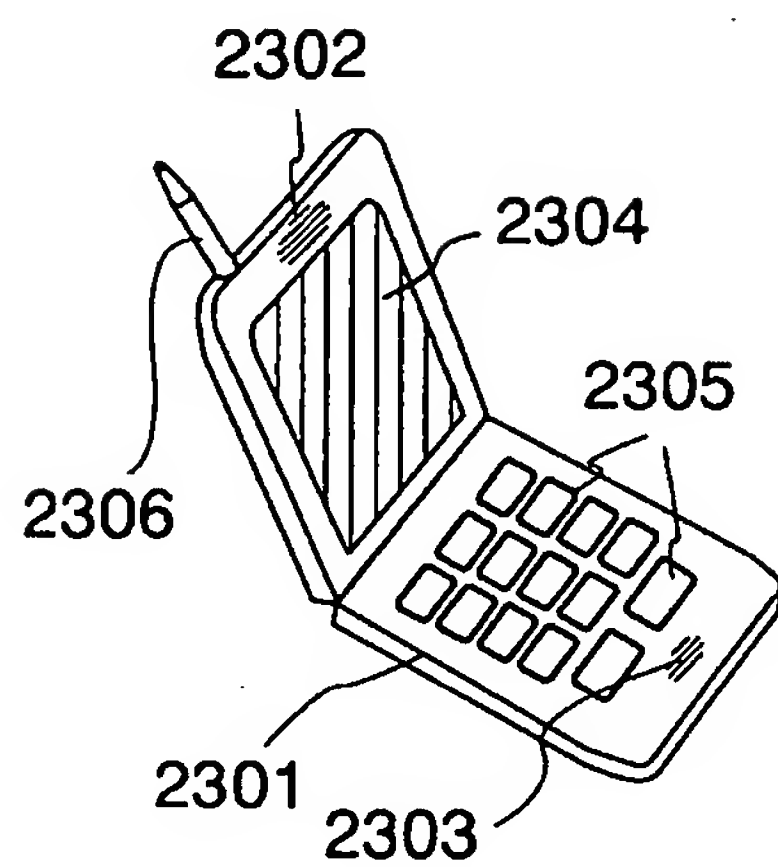


FIG. 21D

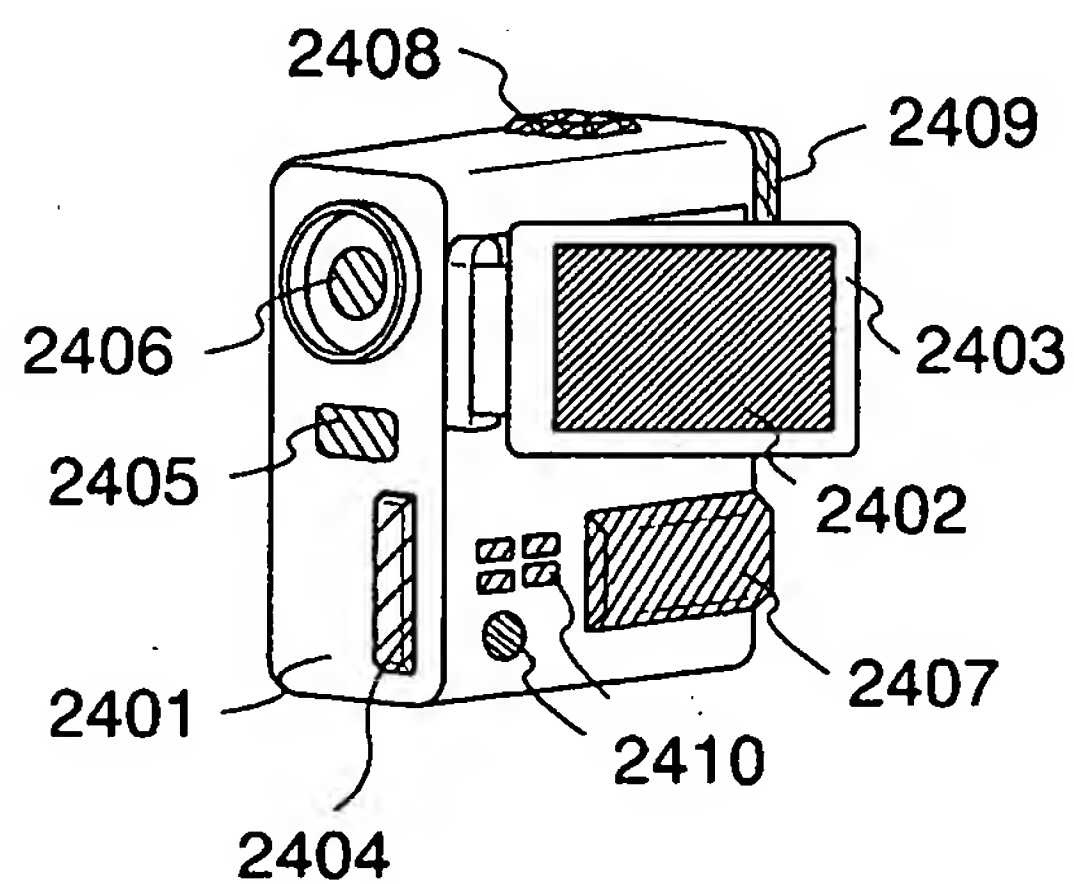


FIG. 22

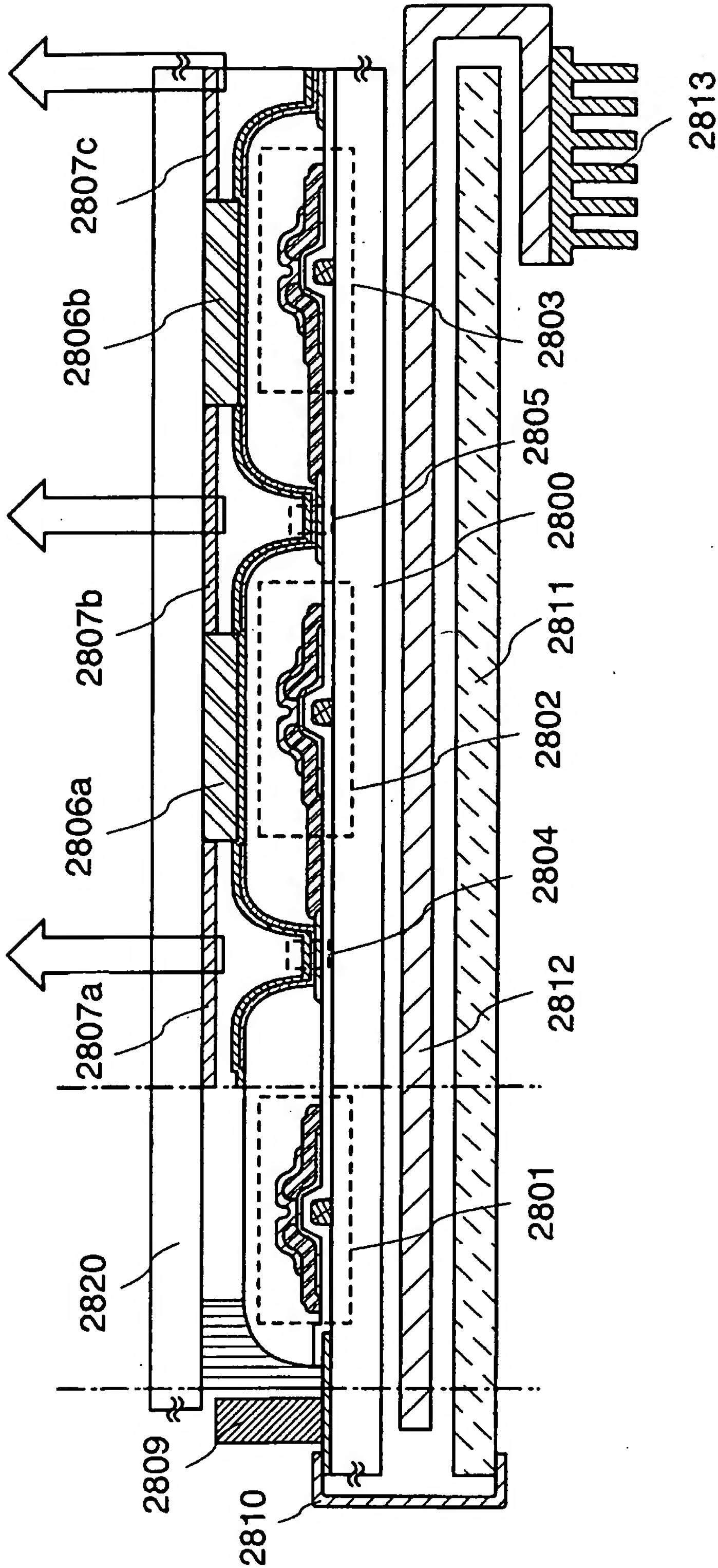


FIG. 23

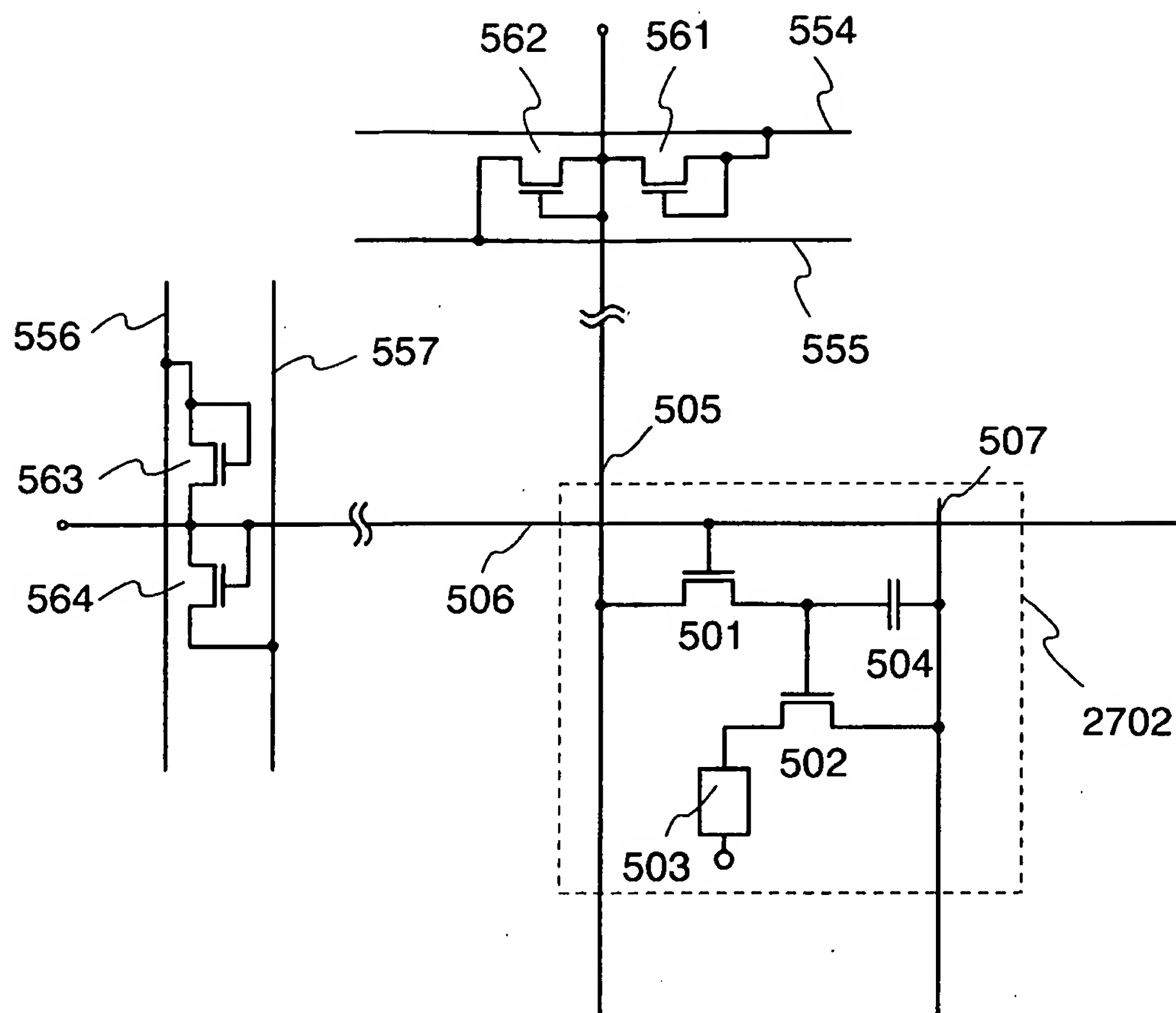


FIG. 24

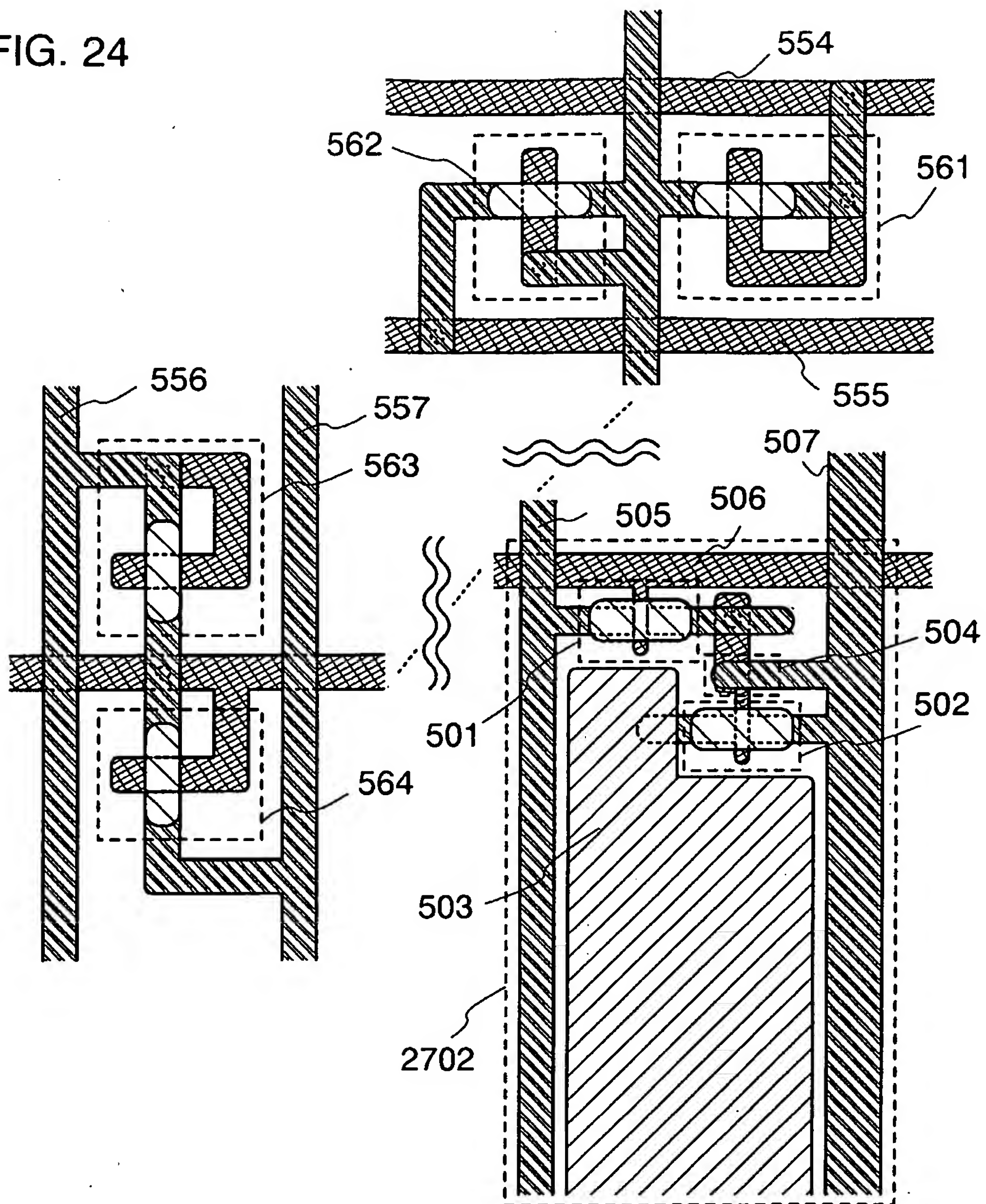


FIG. 25

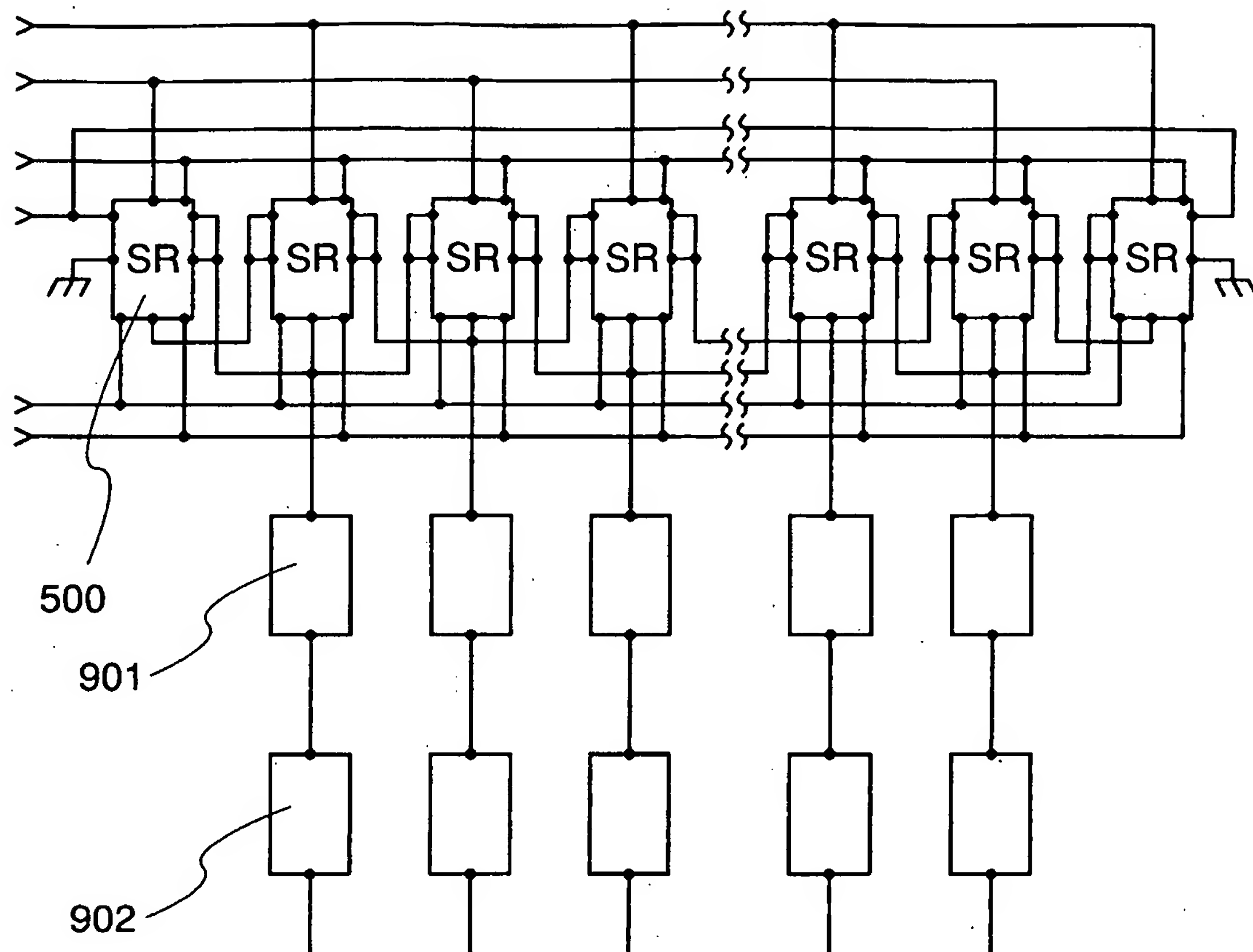


FIG. 26

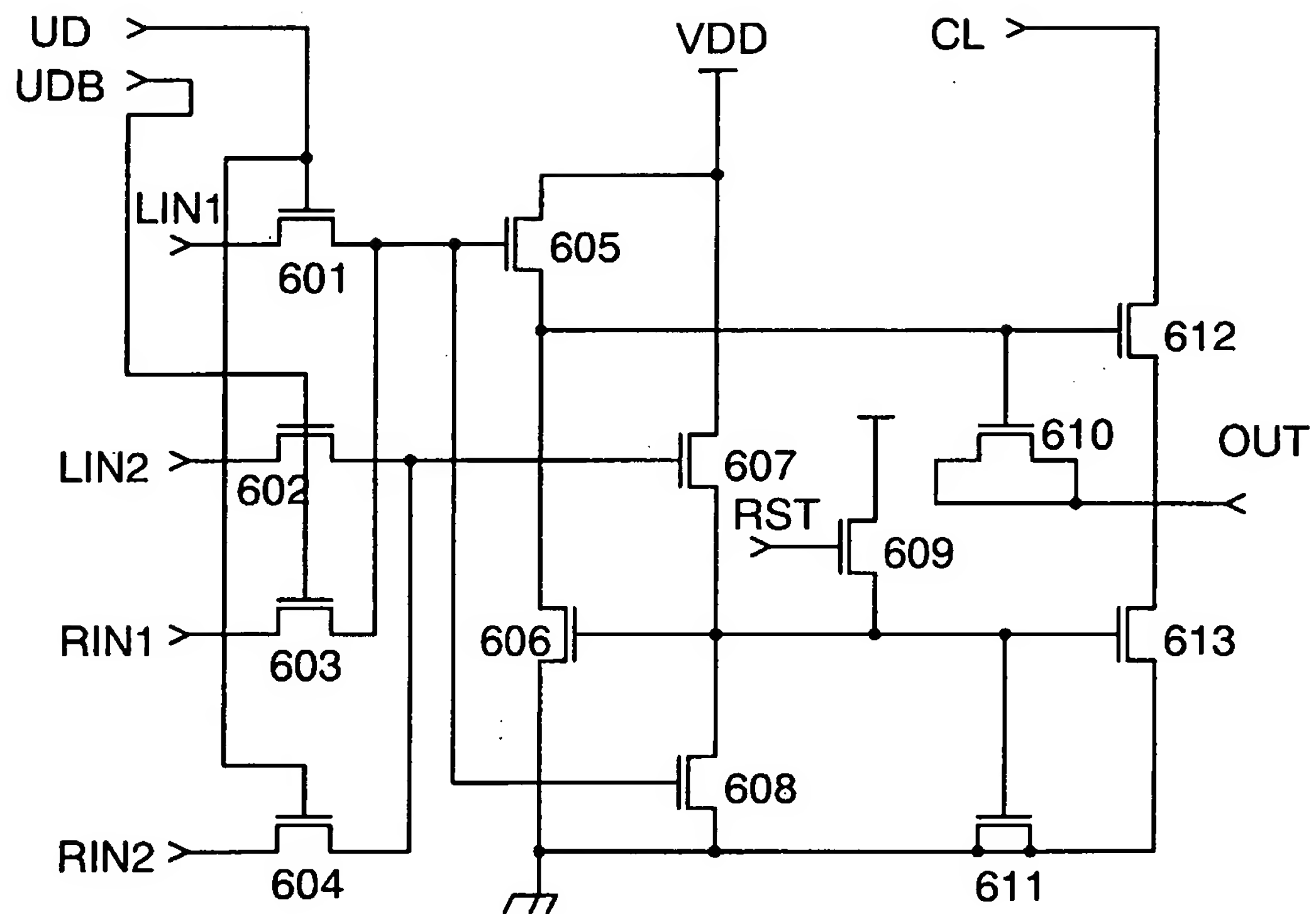


FIG. 27

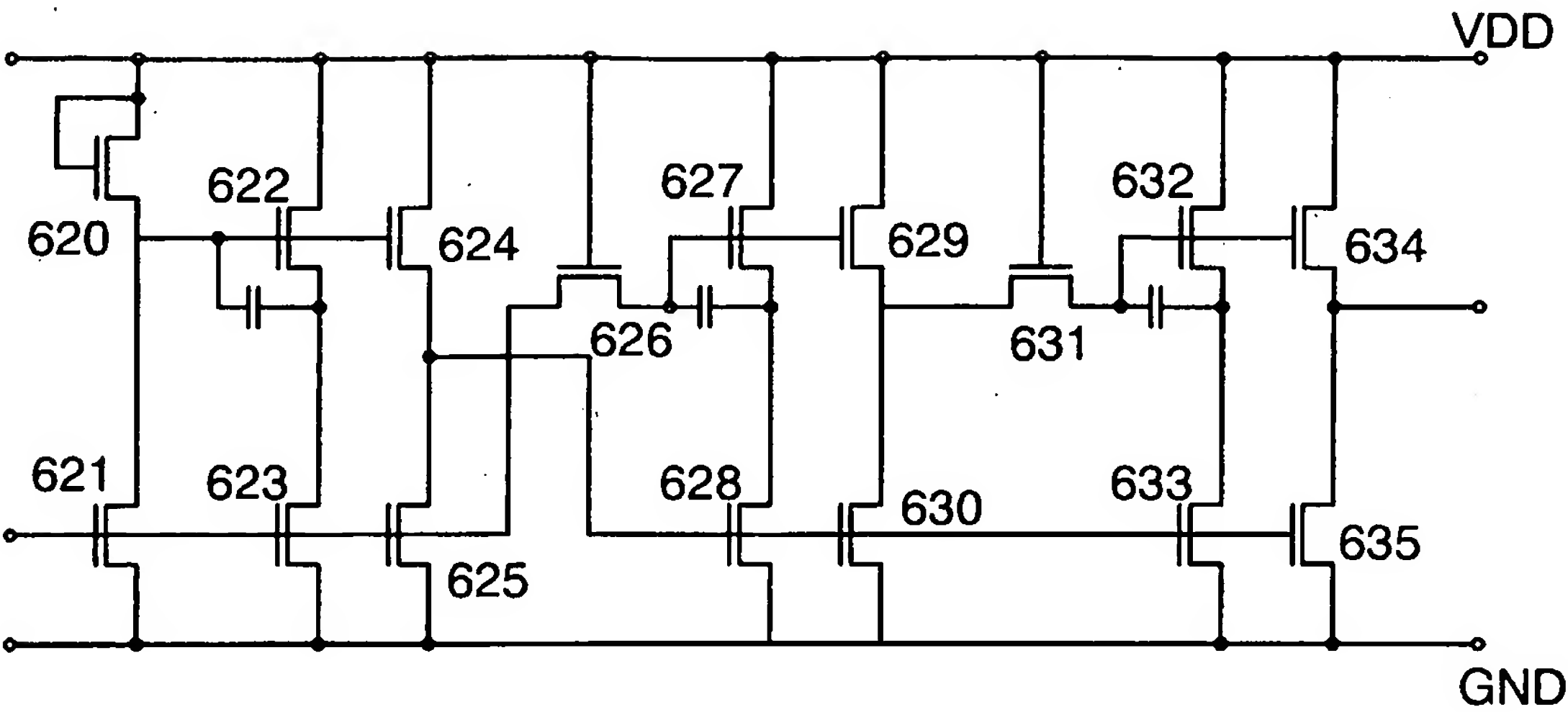


FIG. 28

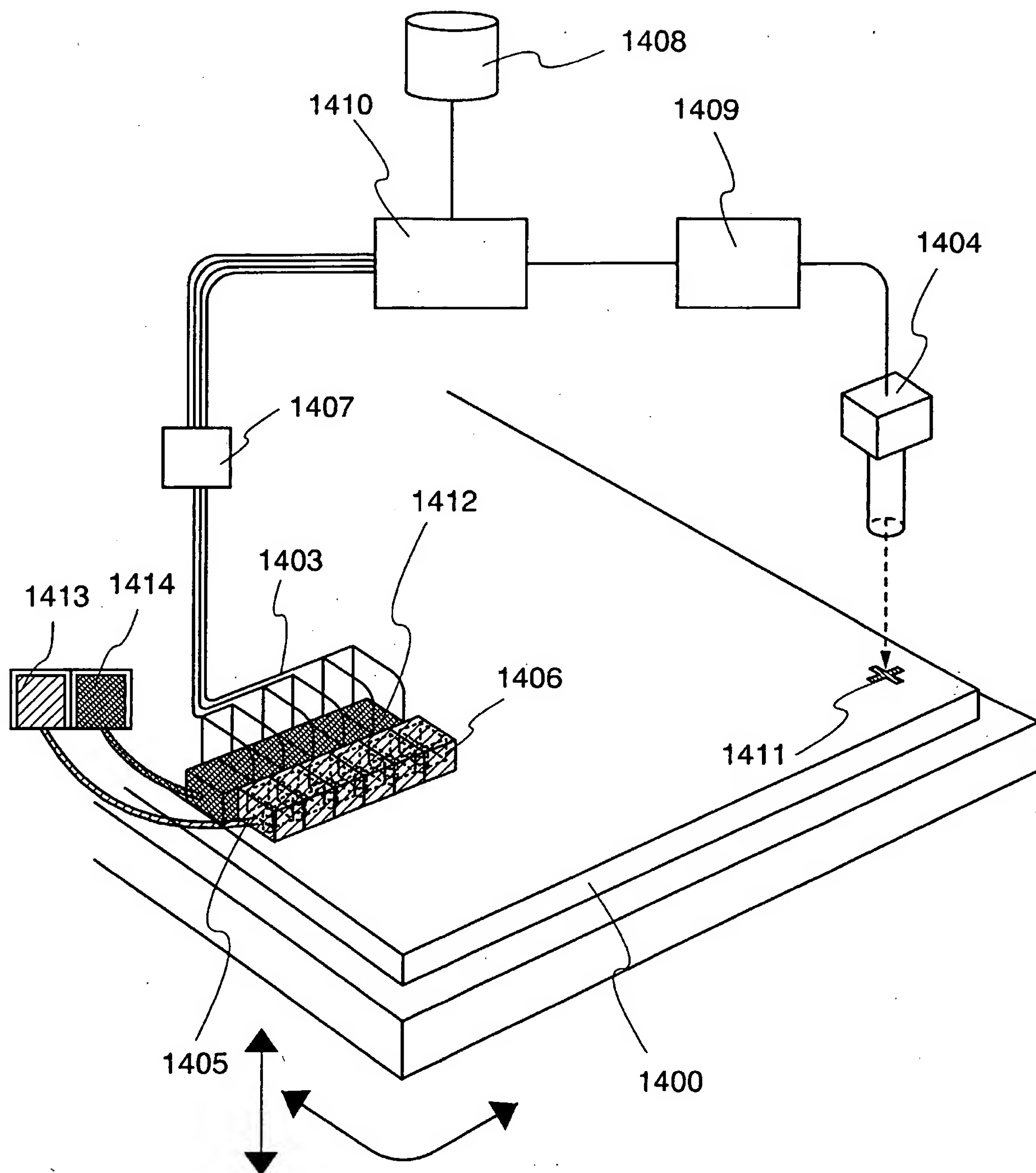


FIG. 29

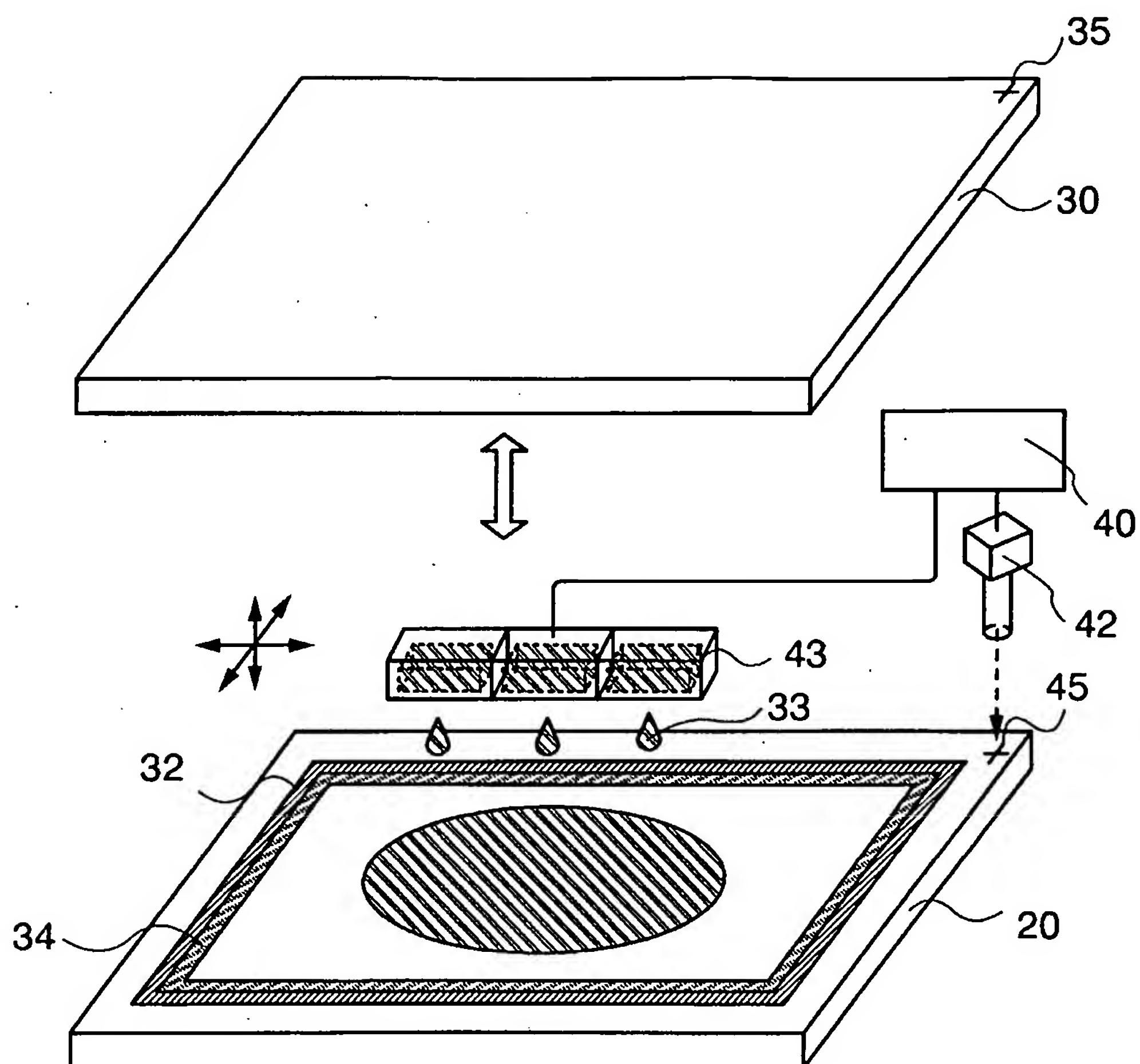


FIG. 30A

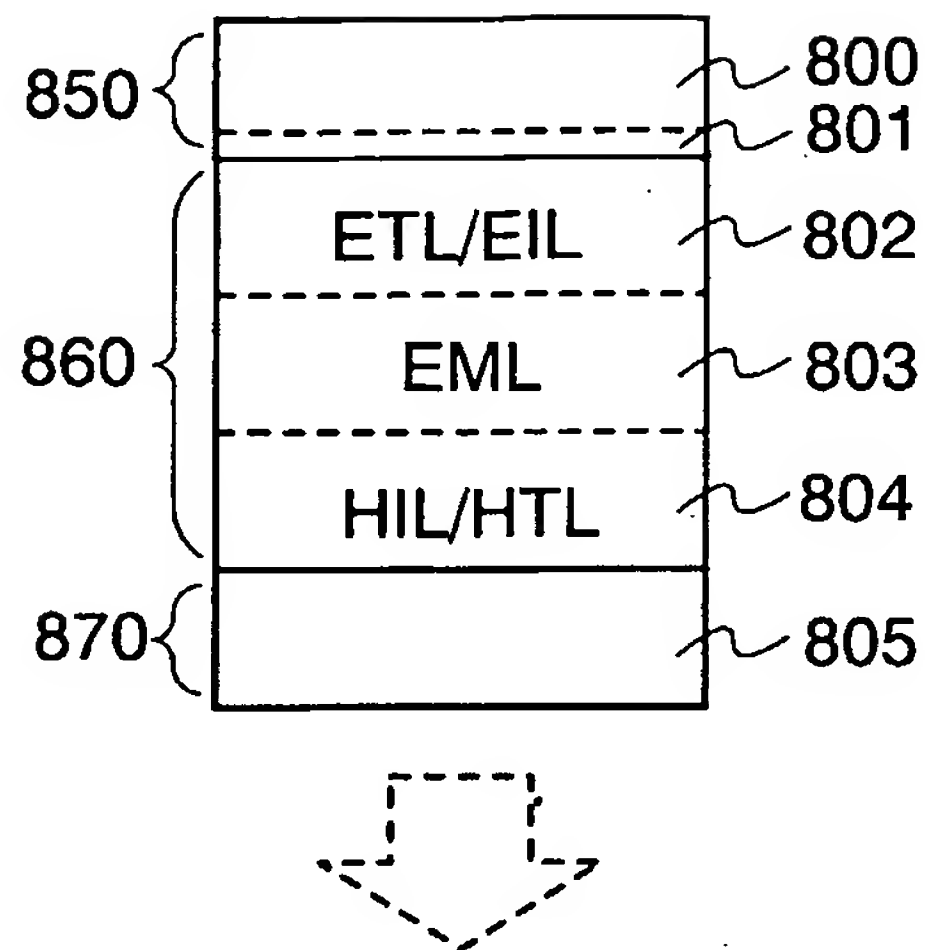


FIG. 30B

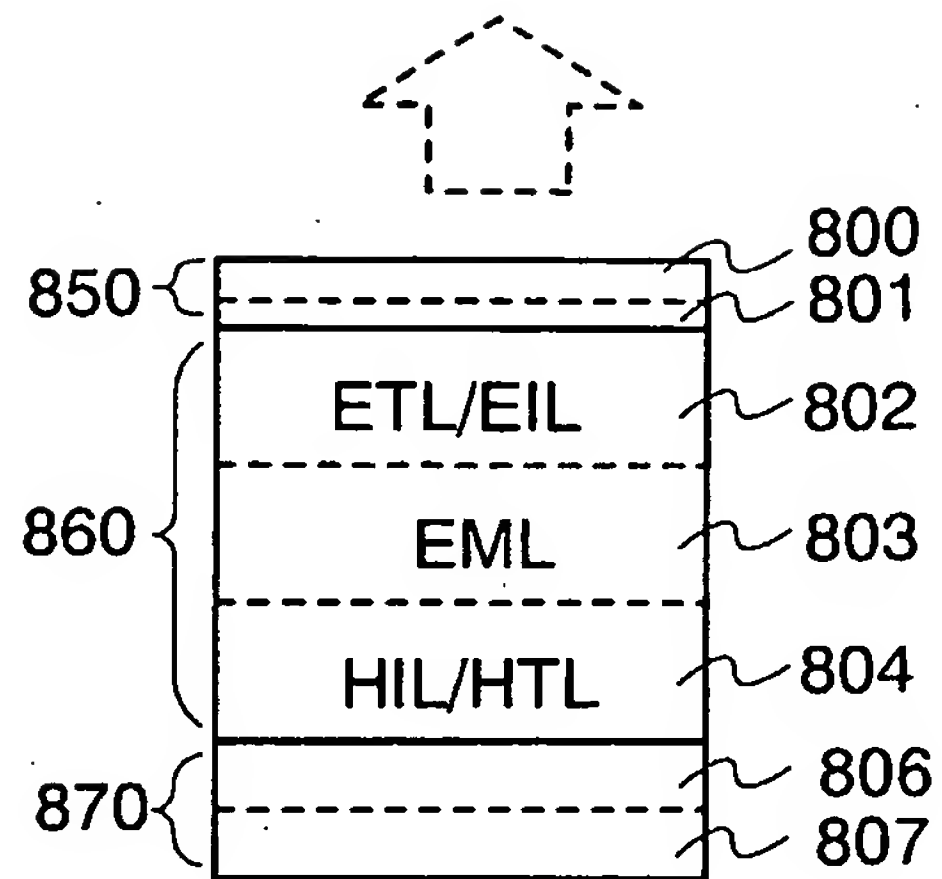


FIG. 30C

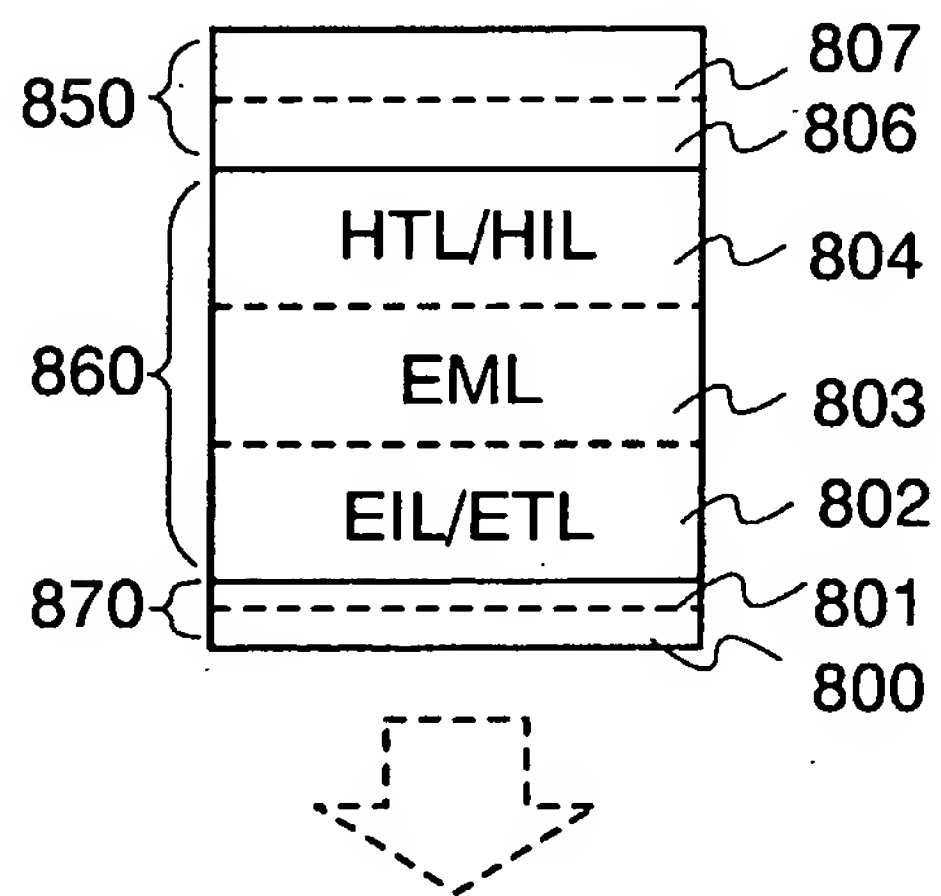
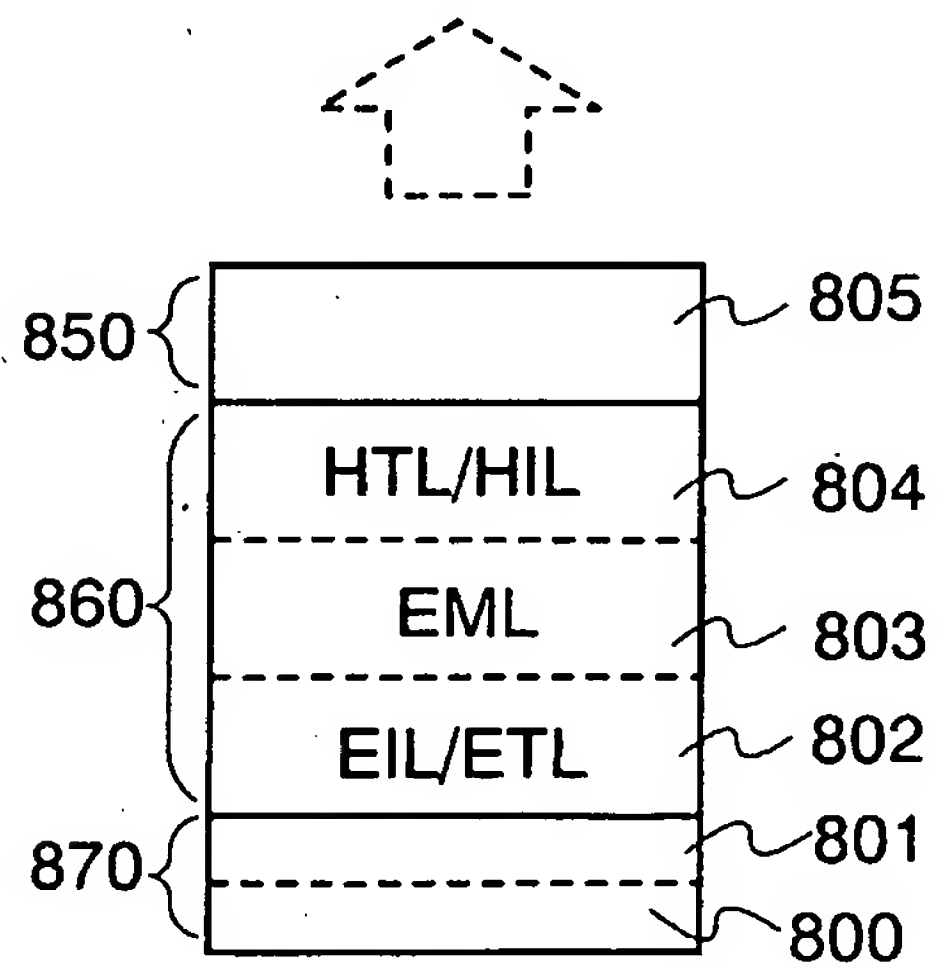


FIG. 30D



EXPLANATION OF REFERENCE

- 5 20: counter substrate, 30: TFT substrate, 32: sealant, 33: liquid crystal, 34: barrier layer, 35: marker, 40: control device, 42: image-taking means, 43: head, 45: marker, 50: substrate, 51: compound having low wettability, 52: substance having low wettability, 53: light-absorbing material, 54: discharge device, 55: droplet, 56: light source, 57a: high-wettability region, 57b: high-wettability region, 58: low-wettability region, 59:
- 10 light, 61: compound having low wettability, 63: light-absorbing material, 64: discharge device, 65: droplet, 66: light, 67a: high-wettability region, 67b: high-wettability region, 68: low-wettability region, 70: mask, 71: low-wettability region; 72a: high-wettability region, 72b: high-wettability region, 73: droplet discharge device, 74: droplet, 75a: pattern, 75b: pattern, 100: substrate, 101a: compound having low wettability, 101b:
- 15 compound having low wettability, 103: gate electrode layer, 104: gate electrode layer, 106: gate insulating layer, 107: semiconductor layer, 108: semiconductor layer, 111: source/drain electrode layer, 112: source/drain electrode layer, 113: source/drain electrode layer, 114: source/drain electrode layer, 117: first electrode layer, 121: insulating layer, 122: electroluminescent layer, 123: second electrode layer, 145:
- 20 through-hole, 150: low-wettability region, 151a: high-wettability region, 151b: high-wettability region, 152: low-wettability region, 153a: high-wettability region, 153b: high-wettability region, 160: connection wiring layer, 161: connection wiring layer, 162: connection wiring layer, 163: connection wiring layer, 170a: light source, 170b: light source, 171a: light, 171b: light, 180a: droplet discharge device, 180b:
- 25 droplet discharge device, 300: substrate, 301: high-wettability region, 302a: low-wettability region, 302b: low-wettability region, 303: gate electrode layer, 305: gate insulating layer, 306: semiconductor layer, 307: n-type semiconductor layer, 308: source/drain electrode layer, 311: pixel electrode layer, 312: insulating layer, 320: liquid crystal layer, 321: insulating layer, 322: coloring layer, 323: conductive layer, 324:
- 30 counter substrate, 325: polarizing plate, 330: source/drain electrode layer, 345:

through-hole, 350: compound having low wettability, 370: light source, 371: light, 381:
droplet discharge device, 401: TFT, 402: capacitor element, 403: TFT, 404: TFT, 405:
5 light emitting element, 406: TFT, 410: signal line, 411: power supply line, 412: power
supply line, 413: power supply line, 414: scanning line, 415: power supply line, 416:
scanning line, 441: TFT, 442: capacitor element, 443: TFT, 444: light emitting element,
445: TFT, 450: signal line, 451: power supply line, 452: power supply line, 453:
scanning line, 454: scanning line, 460: substrate, 461: thin film transistor, 462:
10 source/drain electrode layer, 463: first electrode layer, 464: electroluminescent layer,
465: second electrode layer, 470: substrate, 471: thin film transistor, 472: first electrode
layer, 473: electroluminescent layer, 474: second electrode layer, 477: source/drain
electrode layer, 478: insulating layer, 480: substrate, 481: thin film transistor, 484: first
electrode layer, 485: electroluminescent layer, 486: second electrode layer, 487:
15 source/drain electrode layer, 490: substance including light-absorbing material, 491:
low-wettability region, 492a: high-wettability region, 492b: high-wettability region,
493: gate electrode layer, 494: semiconductor layer, 495: n-type semiconductor layer,
496: channel protective layer, 497: gate insulating layer, 498: insulating layer, 500:
block, 501: TFT, 502: TFT, 503: light emitting element, 504: capacitor element, 505:
20 source/drain wiring layer, 554: common potential line, 555: common potential line, 561:
protective diode, 562: protective diode, 601: TFT, 901: buffer circuit, 902: pixel, 1400:
substrate, 1403: droplet discharge means, 1404: image-taking means, 1405: head, 1407:
control means, 1408: storage medium, 1409: image processing means, 1410: computer,
1411: marker, 1412: head, 2001: chassis, 2002: display panel, 2003: main screen, 2004:
25 modem, 2005: receiver, 2006: remote control device, 2007: display portion, 2008:
sub-screen, 2009: speaker portion, 2010: chassis, 2011: display portion, 2012: keyboard
portion, 2013: speaker portion, 2101: main body, 2102: chassis, 2103: display portion,
2104: keyboard, 2105: external connection port, 2106: pointing mouse, 2201: main
body, 2202: chassis, 2203: display portion A, 2204: display portion B, 2205: recording
30 medium (such as a DVD) reading portion, 2206: operation keys, 2207: speaker portion,

2301: main body, 2302: audio output portion, 2303: audio input portion, 2304: display
portion, 2305: operation switches, 2306: antenna, 2401: main body, 2402: display
5 portion, 2403: chassis, 2404: external connection port, 2405: remote control receiving
portion, 2406: receiving portion, 2407: battery, 2408: audio input portion, 2409:
eyepiece portion, 2410: operation keys, 2600: TFT substrate, 2601: counter substrate,
2602: sealant, 2603: pixel portion, 2604: liquid crystal layer, 2605: coloring layer, 2606:
polarizing plate, 2607: polarizing plate, 2608: driver circuit, 2609: flexible wiring
10 substrate, 2610: cold cathode tube, 2611: reflection plate, 2612: circuit substrate, 2613:
optical film, 2700: substrate, 2701: pixel portion, 2702: pixel, 2703: scanning line input
terminal, 2704: signal line input terminal, 2750: FPC, 2751: driver IC, 2800: TFT
substrate, 2801: protective circuit portion, 2802: TFT, 2803: TFT, 2804: light emitting
element, 2805: light emitting element, 2806a: spacer, 2806b: spacer, 2807a: coloring
15 layer, 2807b: coloring layer, 2807c: coloring layer, 2809: driving circuit, 2810: wiring
substrate, 2812: heat sink, 2813: heat pipe, 2820: sealing substrate, 3300: element
substrate, 3301: pixel portion, 3302: pixel, 3303: sealant, 3304a: desiccant, 3304b:
desiccant, 3305: desiccant, 3306a: gate wiring layer, 3306b: gate wiring layer, 3307:
filler, 3308: source wiring layer, 3310: sealing substrate, 3350: FPC, 3351: driver IC,
20 3601: anti-reflective film, 3602: polarizing plate, 3603: retardation film, 3604:
retardation film, 3605: insulating layer, 3700: substrate, 3701: pixel portion, 3702:
scanning line driver circuit, 3704: signal line input terminal, 4700: substrate, 4701: pixel
portion, 4702: scanning line driver circuit, 4704: signal line driver circuit